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(74) Agent: **TATEISHI, Atsuji**; TATEISHI & CO., Karakida Center Bldg., 1-53-9, Karakida, Tama-shi, Tokyo, 2060035 (JP).

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(71) Applicant (for all designated States except US): **NIKON CORPORATION** [JP/JP]; 12-1, Yurakucho 1-chome, Chiyoda-ku, Tokyo, 1008331 (JP).

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(72) Inventors; and

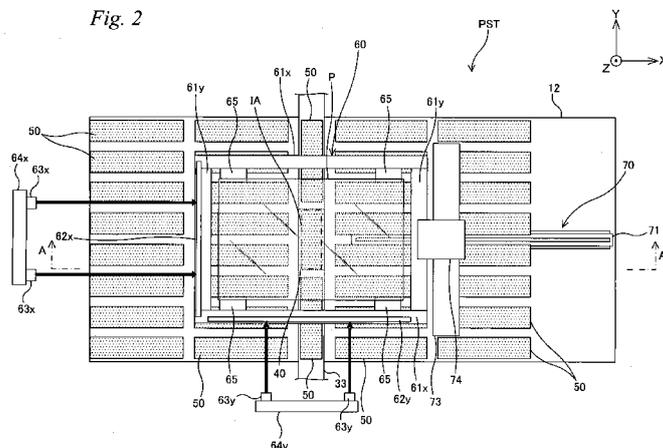
(75) Inventors/Applicants (for US only): **AOKI, Yasuo** [JP/JP]; c/o NIKON CORPORATION, 12-1, Yurakucho 1-chome, Chiyoda-ku, Tokyo, 1008331 (JP). **HAMADA, Tomohide** [JP/JP]; c/o NIKON CORPORATION, 12-1, Yurakucho 1-chome, Chiyoda-ku, Tokyo, 1008331 (JP). **SHIRASU, Hiroshi** [JP/JP]; c/o NIKON CORPORATION, 12-1, Yurakucho 1-chome, Chiyoda-ku, Tokyo, 1008331 (JP). **TOGUCHI, Manabu** [JP/JP]; c/o NIKON CORPORATION, 12-1, Yurakucho 1-chome, Chiyoda-ku, Tokyo, 1008331 (JP).

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(54) Title: OBJECT PROCESSING APPARATUS, EXPOSURE APPARATUS AND EXPOSURE METHOD, AND DEVICE MANUFACTURING METHOD

Fig. 2



(57) Abstract: A plurality of air levitation units (50) that jet air to the lower surface of a substrate (P) are placed below the substrate (P), and the substrate (P) is supported in a noncontact manner so as to be substantially horizontal. Further, a portion subject to exposure of the substrate (P) is held by a fixed-point stage (40) from below in a noncontact manner, and the surface position of the portion subject to exposure is adjusted in a pinpoint manner. Accordingly, exposure can be performed on the substrate (P) with high precision, and a configuration of a substrate stage device (PST) can be simplified.

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Description

Title of Invention

**OBJECT PROCESSING APPARATUS, EXPOSURE APPARATUS AND
5 EXPOSURE METHOD, AND DEVICE MANUFACTURING METHOD**

Technical Field

The present invention relates to object processing apparatuses, exposure apparatuses and exposure methods, and
10 device manufacturing methods, and more particularly to an object processing apparatus that performs predetermined processing with respect to a tabular object, an exposure apparatus and an exposure method to expose the object with an energy beam, and a device manufacturing method that uses
15 any one of the object processing apparatus, the exposure apparatus and the exposure method.

Background Art

Conventionally, in a lithography process for
20 manufacturing electron devices (microdevices) such as liquid crystal display elements or semiconductor devices (integrated circuits or the like), an exposure apparatus such as a projection exposure apparatus by a step-and-repeat method (a so-called stepper), or a projection exposure apparatus by a
25 step-and-scan method (a so-called scanning stepper (which is also called a scanner)) is mainly used.

In this type of the exposure apparatus, a substrate such as a glass plate or a wafer whose surface is coated with a photosensitive agent (hereinafter, generically referred to

as a substrate), which serves as an exposure subject, is mounted on a substrate stage device. And, a mask (or a reticle) on which a circuit pattern is formed is irradiated with exposure light and the exposure light via the mask is irradiated on a substrate via an optical system such as a projection lens, and thereby the circuit pattern is transferred onto the substrate (e.g. refer to PTL1 (and PTL2 corresponding to PTL1)).

In recent years, however, a substrate that is an exposure subject in an exposure apparatus, especially, a substrate for liquid crystal display element (a rectangular glass substrate) has tended to grow in size, for example, the length of a side of the substrate has been increased to 3 m or more, and accordingly, a stage device of the exposure apparatus has also grown in size, and its weight has also increased. Therefore, the development of a stage device has been desired that can guide an exposure subject (substrate) at high speed and with high precision and, further, has a simple configuration with which the size and weight can be reduced.

Citation List

Patent Literature

[PTL 1] PCT International Publication No. 2008/129762

[PTL 2] U.S. Patent Application Publication No.
2010/0018950

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Summary of Invention

According to a first aspect of the present invention, there is provided an object processing apparatus that performs predetermined processing to a tabular object placed along a

predetermined two-dimensional plane that includes a first axis and a second axis orthogonal to each other, the apparatus comprising: an executing device that executes a predetermined operation on a partial area on one surface side of the object;
5 an adjustment device which has a holding surface that holds a section, including the partial area, of the object in a noncontact state from below the object, and which adjusts a position of the section in a direction intersecting the two-dimensional plane; and a noncontact support device that
10 supports the object in a noncontact manner from below, with its support surface made to be opposed to the other area, excluding the section held by the adjustment device, of the object.

With this apparatus, the tabular object is supported in
15 a noncontact manner from below by the noncontact support device. Further, a predetermined operation is performed to a section of the object by the executing device and the section to which the predetermined operation is performed is especially held in a noncontact manner from below by the adjustment device
20 and the position of the section is adjusted in the direction intersecting the two-dimensional plane. Consequently, the predetermined processing can be performed to the object with high accuracy. Further, since the adjustment device adjusts only the section, to which the predetermined operation is
25 performed, in a pinpoint manner, the apparatus configuration can be simplified compared with the case where the position of the entire object is adjusted in the direction intersecting the two-dimensional plane.

According to a second aspect of the present invention,

there is provided an exposure apparatus that exposes an object by irradiating the object with an energy beam and forms a predetermined pattern on the object, the apparatus comprising: a fixed-point stage which includes a member that holds a section, including a partial area on which the energy beam is irradiated, of the object placed along a predetermined two-dimensional plane that includes a first axis and a second axis orthogonal to each other, in a noncontact state from below the object, and which adjusts a position of the section in a direction intersecting the two-dimensional plane; and a noncontact support device that supports the object in a noncontact manner from below, with its support surface made to be opposed to the other area, excluding the section held by the holding surface, of the object.

With this apparatus, the tabular object is supported in a noncontact manner from below by the noncontact support device. Further, a section, including a partial area on which the energy beam is irradiated, of the object is especially held in a noncontact manner from below by the fixed-point stage, and the position of the section in the direction intersecting the two-dimensional plane is adjusted. Consequently, the object can be exposed with high accuracy. Further, since the fixed-point stage adjusts only the section, on which the energy beam is irradiated, of the object in a pinpoint manner, the apparatus configuration can be simplified compared with the case where the position of the object as a whole is adjusted in the direction intersecting the two-dimensional plane.

According to a third aspect of the present invention, there is provided a device manufacturing method, comprising:

exposing the object using the object processing apparatus or the exposure apparatus of the present invention; and developing the exposed object.

In this case, there is provided a manufacturing method of manufacturing a flat-panel display as a device, by using a substrate for a flat-panel display as an object.

According to a fourth aspect of the present invention, there is provided an exposure method of exposing an object by irradiating the object with an energy beam and forming a predetermined pattern on the object, the method comprising: holding a section, including a partial area on which the energy beam is irradiated, of the object placed along a predetermined two-dimensional plane that includes a first axis and a second axis orthogonal to each other, in a noncontact state from below the object by a holding member whose position within the two-dimensional plane is fixed, and adjusting a position of the section in a direction intersecting the two-dimensional plane; and supporting the object in a noncontact manner from below, with a support surface of a support member made to be opposed to the other area, excluding the section held by the holding member, of the object.

With this method, the object is supported in a noncontact manner from below by the support member. Further, a section, including a partial area on which the energy beam is irradiated, of the object is especially held in a noncontact manner from below by the holding member whose position within the two-dimensional plane is fixed, and the position of the section in the direction intersecting the two-dimensional plane is adjusted. Consequently, the object can be exposed with high

accuracy. Further, the holding member adjusts only the section, on which the energy beam is irradiated, of the object in a pinpoint manner.

According to a fifth aspect of the present invention, there is provided a device manufacturing method, comprising: exposing the object using the exposure method of the present invention; and developing the exposed object.

Brief Description of Drawings

10 Fig. 1 is a view showing a schematic configuration of a liquid crystal exposure apparatus of a first embodiment.

Fig. 2 is a plan view of a substrate stage device which the liquid crystal exposure apparatus of Fig. 1 has.

15 Fig. 3 is a cross-sectional view taken along the line A-A of Fig. 2.

Fig. 4 is a cross-sectional view of a fixed-point stage which the substrate stage device of Fig. 2 has.

20 Fig. 5(A) is a plan view enlargedly showing a part of a substrate holding frame which the substrate stage device of Fig. 2 has, and Fig. 5(B) is a cross-sectional view taken along the line B-B of Fig. 5(A).

Figs. 6(A) to 6(C) are views used to explain an operation of the substrate stage device when exposure processing is performed on a substrate.

25 Fig. 7(A) is a plan view of a substrate stage device related to a second embodiment, and Fig. 7(B) is a cross-sectional view taken along the line C-C of Fig. 7(A).

Fig. 8 is a plan view of a substrate stage device related to a third embodiment.

Fig. 9 is a plan view of a substrate stage device related to a fourth embodiment.

Fig. 10 is a cross-sectional view taken along the line D-D of Fig. 9.

5 Fig. 11 is a plan view of a substrate stage device related to a fifth embodiment.

Fig. 12 is a cross-sectional view taken along the line E-E of Fig. 11.

10 Fig. 13 is a plan view of a substrate stage device related to a sixth embodiment.

Fig. 14 is a plan view of a substrate stage device related to a seventh embodiment.

Fig. 15 is a side view of the substrate stage device of Fig. 14 when viewed from the +X side.

15 Fig. 16 is a plan view of a substrate stage device related to an eighth embodiment.

Fig. 17 is a view showing a schematic configuration of a substrate inspecting apparatus related to a ninth embodiment.

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Description of Embodiments

- First Embodiment

A first embodiment of the present invention is described below, with reference to Figs. 1 to 6(C).

25 Fig. 1 shows a schematic configuration of a liquid crystal exposure apparatus 10 related to the first embodiment that is used in manufacturing of flat-panel displays, for example, liquid crystal display devices (liquid crystal panels) or the like. Liquid crystal exposure apparatus 10 is

a projection exposure apparatus by a step-and-scan method, in which a rectangular glass substrate P (hereinafter, simply referred to as a substrate P) that is used for a display panel of a liquid crystal display device serves as an exposure
5 subject, which is a so-called scanner.

As shown in Fig. 1, liquid crystal exposure apparatus
10 is equipped with illumination system IOP, a mask stage MST that holds a mask M, a projection optical system PL, a body BD on which mask stage MST and projection optical system PL
10 described above and the like are mounted, a substrate stage device PST that holds substrate P, and their control system, and the like. In the description below, the explanation is given assuming that a direction in which mask M and substrate
P are scanned relative to projection optical system PL,
15 respectively, during exposure is an X-axis direction, a direction orthogonal to the X-axis direction within a horizontal plane is a Y-axis direction, and a direction orthogonal to the X-axis and the Y-axis is a Z-axis direction, and rotational (tilt) directions around the X-axis, Y-axis
20 and Z-axis are θ_x , θ_y and θ_z directions, respectively.

Illumination system IOP is configured similar to the illumination system that is disclosed in, for example, U.S. Patent No. 6,552,775 and the like. More specifically, illumination system IOP irradiates mask M with a light emitted
25 from a light source that is not illustrated (e.g. a mercury lamp), as an illumination light for exposure (illumination light) IL, via a reflection mirror, a dichroic mirror, a shutter, a wavelength selecting filter, various types of lenses and the like, which are not illustrated. As

illumination light IL, for example, a light such as an i-line (with a wavelength of 365 nm), a g-line (with a wavelength of 436 nm) or an h-line (with a wavelength of 405 nm) (or a synthetic light of the i-line, the g-line and the h-line described above) is used. Further, the wavelength of illumination light IL can be appropriately switched by the wavelength selecting filter, for example, according to the required resolution.

On mask stage MST, mask M having a pattern surface (the lower surface in Fig. 1) on which a circuit pattern and the like are formed is fixed by, for example, vacuum adsorption (or electrostatic adsorption). Mask stage MST is supported by levitation in a noncontact state, for example, via air bearings that are not illustrated, above a pair of mask stage guides 35 that are fixed to the upper surface of a barrel surface plate 31 that is a part of body BD to be described later on. Mask stage MST is driven in a scanning direction (the X-axis direction) with a predetermined stroke and also is finely driven in the Y-axis direction and the θz direction as needed, above the pair of mask stage guides 35, by a mask stage driving system (not illustrated) that includes, for example, a linear motor. Positional information of mask stage MST within the XY plane (which includes rotational information in the θz direction) is measured by a mask interferometer system that includes a laser interferometer that is not illustrated.

Projection optical system PL is supported below mask stage MST in Fig. 1, by barrel surface plate 31. Projection optical system PL of the present embodiment has a configuration

similar to the projection optical system disclosed in, for example, U.S. Patent No. 6,552,775. More specifically, projection optical system PL includes a plurality of projection optical systems that have projection areas with a predetermined shape, e.g. a trapezoidal shape, of the pattern image of mask M that are placed in a zigzag shape (multi-lens projection optical systems), and functions equivalently to a projection optical system that has a rectangular single image field whose longitudinal direction is in the Y-axis direction.

5

10 In the present embodiment, as each of the plurality of projection optical systems, for example, a both-side telecentric equal-magnification system that forms an erected normal image is used. Further, in the description below, the plurality of projection areas placed in the zigzag shape of projection optical system PL are collectively referred to as

15 an exposure area IA (see Fig. 2).

Therefore, when an illumination area on mask M is illuminated with illumination light IL from illumination system IOP, by illumination lights IL that have passed through mask M whose pattern surface is placed substantially coincident with the first plane (object plane) of projection optical system PL, a projected image (partial erected image) of a circuit pattern of mask M within the illumination area is formed on an irradiation area (exposure area IA) of illumination light IL, which is conjugate to the illumination area, on substrate P which is placed on the second plane (image plane) side of projection optical system PL and whose surface is coated with a resist (sensitive agent), via projection optical system PL. Then, by moving mask M relative to the

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illumination area (illumination light IL) in the scanning direction (X-axis direction) and also moving substrate P relative to exposure area IA (illumination light IL) in the scanning direction (X-axis direction) by synchronous drive of mask stage MST and substrate stage device PST, scanning exposure of one shot area (divided area) on substrate P is performed, and a pattern of mask M (mask pattern) is transferred onto the shot area. More specifically, in the present embodiment, a pattern of mask M is generated on substrate P by illumination system IOP and projection optical system PL, and the pattern is formed on substrate P by exposure of a sensitive layer (resist layer) on substrate P with illumination light IL.

As disclosed in, for example, U.S. Patent Application Publication No. 2008/0030702 and the like, body BD has barrel surface plate 31 described earlier, and a pair of support walls 32 that support the ends on the +Y side and the -Y side of barrel surface plate 31 from below, on a floor surface F. Each of the pair of support walls 32 is supported on floor surface F via a vibration isolation table 34 that includes, for example, an air spring, and body BD is separated from floor surface F in terms of vibration. Further, between the pair of support walls 32, a Y beam 33 made up of a member having a rectangular sectional shape (see Fig. 3) arranged extending parallel to the Y-axis is installed. Between the lower surface of Y beam 33 and the upper surface of a surface plate 12 to be described later on, a predetermined clearance is formed. More specifically, Y beam 33 and surface plate 12 are noncontact and are separated in terms of vibration.

Substrate stage device PST is equipped with surface plate 12 installed on floor surface F, a fixed-point stage 40 (see Fig. 2) that holds substrate P from below in a noncontact manner, directly under exposure area IA (see Fig. 2), a plurality of air levitation units 50 installed on surface plate 12, a substrate holding frame 60 that holds substrate P and a drive unit 70 that drives substrate holding frame 60 in the X-axis direction and the Y-axis direction (along the XY plane).

10 As shown in Fig. 2, surface plate 12 is made up of a member having a rectangular plate shape whose longitudinal direction is in the X-axis direction in a planar view (when viewed from the +Z side).

Fixed-point stage 40 is placed at a position that is slightly on the -X side from the center on surface plate 12. Further, as shown in Fig. 4, fixed-point stage 40 is equipped with a weight canceller 42 mounted on Y beam 33, a chuck member (an air chuck unit) 80 supported by weight canceller 42, an actuator used to drive air chuck unit 80 in a direction intersecting the XY plane, for example, a plurality of Z voice coil motors (hereinafter, shortly referred to as Z-VCMs), and the like.

Weight canceller 42 is equipped with a case 43, for example, fixed to Y beam 33, an air spring 44 housed in the lowermost section inside case 43, and a Z slider 45 supported by air spring 44. Case 43 is made up of a cylinder-like member having a bottom which is opened on the +Z side. Air spring 44 has a bellows 44a made up of a hollow member formed with a rubber-based material, and a pair of plates 44b (e.g. metal

plates) parallel to the XY plane that is placed on (on the +Z side of) and under (on the -Z side of) bellows 44a. The inside of bellows 44a is set to be a positive pressure space whose atmospheric pressure is higher compared with the outside, because a gas is supplied from a gas supplying device that is not illustrated. Weight canceller 42 reduces the load on the plurality of Z-VCMS by cancelling out the weight (a downward force (in the -Z direction) owing to the gravitational acceleration) of substrate P, air chuck unit 80, Z slider 45 and the like with an upward force (in the +Z direction) generated by air spring 44.

Z slider 45 is made up of a columnar member arranged extending parallel to the Z-axis whose lower end is fixed to plate 44b placed on the +Z side of air spring 44. Z slider 45 is connected to the inner wall surface of case 43 via a plurality of parallel plate springs 46. Parallel plate spring 46 has a pair of plate springs parallel to the XY plane that are placed apart in the vertical direction. Parallel plate springs 46 connect Z slider 45 and case 43 at, for example, four positions in total which are positions on the +X side, the -X side, the +Y side and the -Y side of Z slider 45 (the illustration of the parallel plate springs on the +Y side and the -Y side of Z slider 45 is omitted). While relative movement of Z slider 45 with respect to case 43 in directions parallel to the XY plane is restricted owing to the stiffness (extensional stiffness) of the respective parallel plate springs 46, Z slider 45 can be relatively moved with a minute stroke with respect to case 43 in the Z-axis direction owing to the flexibility of the respective parallel plate springs

46. Consequently, Z slider 45 vertically moves with respect to Y beam 33 by the pressure of a gas within bellows 44a being adjusted. Incidentally, a member that generates an upward force used to cancel the weight of substrate P is not limited to the air spring (bellows) described above, but can be an air cylinder, a coil spring, or the like. Further, as a member that restricts the position of the Z slider within the XY plane, for example, a noncontact thrust bearing (e.g. a static gas bearing such as an air bearing) whose bearing surface is opposed to the side surface of the Z slider, or the like can also be used (refer to PCT International Publication No. 2008/129762 (the corresponding U.S. Patent Application Publication No. 2010/0018950)).

Air chuck unit 80 includes a chuck main body 81 that holds by adsorption a portion that corresponds to exposure area IA (portion subject to exposure), of substrate P in a noncontact manner from the lower surface side of substrate P, and a base 82 that supports chuck main body 81 from below. The upper surface (the surface on the +Z side) of chuck main body 81 has a rectangular shape with the Y-axis direction serving as its longitudinal direction in a planar view (see Fig. 2), and the center of the upper surface roughly coincides with the center of exposure area IA. Further, the area size of the upper surface of chuck main body 81 is set larger than exposure area IA, and especially the size in the X-axis direction that is the scan direction is set longer than the size of exposure area IA in the X-axis direction.

Chuck main body 81 has a plurality of gas jetting ports, which are not illustrated, on its upper surface, and supports

substrate P by levitation by jetting a gas supplied from the gas supplying device that is not illustrated, for example, a high-pressure gas toward the lower surface of substrate P. Furthermore, chuck main body 81 has a plurality of gas suctioning ports, which are not illustrated, on the upper surface. A gas suctioning device (vacuum device) that is not illustrated is connected to chuck main body 81, and the gas suctioning device suctions the gas between the upper surface of chuck main body 81 and the lower surface of substrate P via the gas suctioning ports of chuck main body 81, and generates the negative pressure between chuck main body 81 and substrate P. Air chuck unit 80 holds substrate P by adsorption in a noncontact manner using a balance between the pressure of the gas jetted from chuck main body 81 to the lower surface of substrate P and the negative pressure generated when the gas between chuck main body 81 and the lower surface of substrate P is suctioned. In this manner, since air chuck unit 80 places so-called preload on substrate P, the stiffness of the gas (air) membrane formed between chuck main body 81 and substrate P can be increased, and accordingly, even if substrate P has deformation or warpage, the portion subject to exposure, which is located directly under projection optical system PL, of substrate P can surely be redressed along the holding surface of chuck main body 81. However, since air chuck unit 80 does not restrict the position of substrate P within the XY plane, substrate P can relatively move in each of the X-axis direction (scan direction) and the Y-axis direction (step direction) with respect to illumination light IL (see Fig. 1) even if substrate P is in a state held by

adsorption by air chuck unit 80.

As shown in Fig. 5(B), in this embodiment, the flow rate or the pressure of the gas jetted from the upper surface of chuck main body 81 and the flow rate or the pressure of the gas suctioned by the gas suctioning device are set such that a distance D_a (clearance) between the upper surface (substrate holding surface) of chuck main body 81 and the lower surface of substrate P is, for example, around 0.02 mm. Incidentally, the gas jetting ports and the gas suctioning ports can be formed by the mechanical processing, or chuck main body 81 is formed with a porous material and its holes can be used as the gas jetting ports and the gas suctioning ports. The details of the configuration and the functions of this type of the air chuck unit (vacuum preload air bearing) are disclosed in, for example, PCT International Publication No. 2008/121561 and the like.

Referring back to Fig. 4, in the center of the lower surface of base 82, a static gas bearing having a semispherical-shaped bearing surface, e.g. a spherical air bearing 83 is fixed. Spherical air bearing 83 is fitted into a concave section 45a having a semispherical shape that is formed on the end surface on the +Z side (upper surface) of Z slider 45. Accordingly, air chuck unit 80 is supported, by Z slider 45, swingably with respect XY plane (rotatably in the θ_x and θ_y directions). Incidentally, as a structure that supports air chuck unit 80 swingably with respect to the XY plane, a quasi-spherical bearing structure that uses a plurality of air pads (air bearings) that is disclosed in, for example, PCT International Publication No. 2008/129762

(the corresponding U.S. Patent Application Publication No. 2010/0018950) can also be employed, or an elastic hinge device can also be used.

One each of a plurality, four in this embodiment, of the
5 Z-VCMS is arranged on the +X side, the -X side, the +Y side
and the -Y side of weight canceller 42 (as for the Z-VCM on
the -Y side, see Fig. 3, and the illustration of the Z-VCM
on the +Y side is omitted). The four Z-VCMS have the same
configuration and functions except that their setting
10 positions are different. Each of the four Z-VCMS includes a
Z stator 47 fixed to a base frame 85 installed on surface plate
12 and a Z mover 48 fixed to base 82 of air chuck unit 80.

Base frame 85 includes a main section 85a made up of a
plate-shaped member formed so as to have an annular shape in
15 a planar view and a plurality of leg sections 85b that support
main section 85a from below on surface plate 12. Main section
85a is placed above Y beam 33 and weight canceller 42 is
inserted in an opening section formed in the center portion
of main section 85a. Therefore, main section 85a is
20 noncontact with each of Y beam 33 and weight canceller 42.
Each of the plurality (three or more, in this case) of leg
sections 85b is made up of a member arranged extending parallel
to the Z-axis, and the +Z side end of leg section 85b is
connected to main section 85a and the -Z side end is fixed
25 to surface plate 12. The plurality of leg section 85b are
respectively inserted in a plurality of through-holes 33a,
which are formed in Y beam 33 so as to respectively correspond
to the plurality of leg sections 85b and which penetrate in
the Z-axis direction, and the plurality of leg section 85b

are noncontact with Y beam 33.

Z mover 48 is made up of a member having an inverse U-like sectional shape and has a magnetic unit 49 including magnets on each of a pair of opposed surfaces. Meanwhile, Z stator 5 47 has a coil unit including coils (the illustration is omitted) and the coil unit is inserted between a pair of magnetic units 49. The magnitude and the direction of the electric current supplied to the coils of Z stator 47 are controlled by a main controller that is not illustrated, and 10 when the electric current is supplied to the coils of the coil unit, Z mover 48 (i.e. air chuck unit 80) is driven with respect to Z stator 47 (i.e. base frame 85) in the Z-axis direction by the electromagnetic force (Lorentz force) generated by the electromagnetic interaction between the coil unit and the 15 magnetic units. The main controller, which is not illustrated, drives (vertically moves) air chuck unit 80 in the Z-axis direction by synchronously controlling the four Z-VCMs. Further, the main controller swings air chuck unit 80 in arbitrary directions with respect to the XY plane (drives air 20 chuck unit 80 in the θ_x direction and the θ_y direction) by appropriately controlling the magnitude and the direction of the electric current supplied to each of the coils that the four Z stators 47 have. With this operation, fixed-point stage 40 adjusts at least one position of the position in the 25 Z-axis direction and the position in the θ_x and the θ_y directions of the portion subject to exposure of substrate P. Incidentally, while each of the X-axis VCMs, the Y-axis VCMs and the Z-axis VCM in the present embodiment is a voice coil motor by a moving magnet type in which the mover has the

magnetic unit, this is not intended to be limiting, and each of the VCMs can be a voice coil motor by a moving coil type in which the mover has the coil unit. Further, the drive method can be drive methods other than the Lorentz force drive method.

5 In this case, since Z stator 47 of each of the four Z-VCMs is mounted on base frame 85, the reaction force of the drive force which acts on Z stator 47 when air chuck unit 80 is driven in the Z-axis direction, or the θ_x direction and the θ_y direction using the four Z-VCMs is not transmitted to Y beam
10 33. Consequently, when air chuck unit 80 is driven using the Z-VCMs, the operation of weight canceller 42 is not affected at all. Further, because the reaction force of the drive force is not transmitted to body BD that has Y beam 33 as well, the reaction force of the drive force does not affect projection
15 optical system PL and the like when air chuck unit 80 is driven using the Z-VCMs. Incidentally, the number of the Z-VCMs can be three if the three Z-VCMs are arranged, for example, at three noncollinear positions, because the Z-VCMs only should vertically move air chuck unit 80 along the Z-axis direction
20 and swing the air chuck unit in arbitrary directions with respect to the XY plane.

 Positional information of air chuck unit 80 that is driven by the Z-VCMs is obtained using a plurality, e.g. four in the embodiment, of Z sensors 86. One each of Z sensors 86
25 is arranged on the +X side, the -X side, the +Y side and the -Y side of weight canceller 42 so as to correspond to the four Z-VCMs (the illustration of the Z sensors on the +Y side and on the -Y side are omitted). Accordingly, in the present embodiment, the drive point (the point of action of the drive

force) by the Z-VCMS on a driven object (in this case, air chuck unit 80) that is driven by the Z-VCMS and the measurement points by Z sensors 86 are made to be closely arranged, and thereby the stiffness of the driven object between the measurement points and the drive point is increased, which increases the controllability of Z sensors 86. More specifically, Z sensors 86 output the accurate measurement values that correspond to the drive distance by the driven object, thereby decreasing the positioning time. It is desirable for Z sensors 86 to have a short sampling period, from the viewpoint of increasing the controllability.

The four Z sensors 86 are substantially the same sensors. Z sensor 86 configures, together with a target 87 fixed to the lower surface of base 82 of air chuck unit 80, a position sensor by, for example, a capacitance method (or an eddy current method) that obtains the positional information of air chuck unit 80 in the Z-axis direction with Y beam 33 serving as a reference. The main controller, which is not illustrated, constantly obtains positional information of air chuck unit 80 in the Z-axis direction and each of the θ_x and θ_y directions based on the outputs of the four Z sensors 86, and controls the position of the upper surface of air chuck unit 80 by appropriately controlling the four Z-VCMS based on the measurement values. In this case, the final position of air chuck unit 80 is controlled such that the exposure surface (e.g. the resist surface to be the upper surface) of substrate P that passes close to above air chuck unit 80 substantially coincides with the focal position of projection optical system PL (i.e. is within a depth of focus of projection optical system

PL) at all times. While monitoring the position of the upper surface (the surface position) of substrate P with a surface position measuring system (autofocus device) that is not illustrated, the main controller, which is not illustrated, drives and controls air chuck unit 80 using the positional information from Z sensors 86 that have high controllability such that the upper surface of substrate P is constantly located within a depth of focus of projection optical system PL (such that projection optical system PL is focused on the upper surface of substrate P at all times). In this case, the surface position measuring system (autofocus device) has a plurality of measurement points whose positions in the Y-axis direction are different within exposure area IA. For example, at least one measurement point is placed in each projection area. In this case, the plurality of measurement points are placed in two rows spaced apart in the X-axis direction, in accordance with the zigzag-shaped placement of the plurality of projection areas. Consequently, based on the measurement values of the plurality of measurement points (the surface positions), the pitching amount (θ_y rotation) and the rolling amount (θ_x rotation) of substrate P can be obtained, in addition to the Z-position of the substrate P surface of exposure area IA portion. Further, the surface position measuring system can have a measurement point on the outer side of exposure area IA in the Y-axis direction (non-scanning direction), separately from or in addition to the plurality of measurement points. In this case, by using the measurement values of the two measurement points located outermost in the Y-axis direction that include the measurement point located

on the outer side, it becomes possible to more accurately obtain the rolling amount (θ_x rotation). Further, the surface position measuring system can have another measurement point at a position slightly away in the X-axis direction (scanning direction) on the outer side of exposure area IA. In this case, so-called read-ahead control of focus/leveling of substrate P becomes possible. Besides, instead of or in addition to the plurality of measurement points at least one of which is placed in each projection area, the surface position measuring system can have a plurality of measurement points disposed in the Y-axis direction at positions away from exposure area IA in the X-axis direction (scanning direction) (the placement area of such plurality of measurement points corresponds to the position of exposure area IA in the Y-axis direction). In such a case, it becomes possible to perform the focus mapping that acquires the distribution of surface position of substrate P in advance, prior to exposure start, for example, during alignment measurement. During the exposure, the focus/leveling control of substrate P is performed using information obtained in the focus mapping. The focus mapping of a substrate and focus/leveling control of the substrate during exposure using the information of the focus mapping are disclosed in detail in, for example, U.S. Patent Application Publication No. 2008/0088843 and the like.

Incidentally, the number of the Z sensors can be three if the three Z sensors are arranged, for example, at three noncollinear positions, because the Z sensors only should obtain positional information of air chuck unit 80 in the Z-axis direction and each of the θ_x and θ_y directions.

The plurality of air levitation units 50 (e.g. 34 units in this embodiment) prevent the vibration from the outside from being transmitted to substrate P, preventing substrate P from deforming (bending) and breaking because of the self weight, restraining occurrence of size error in each of the X and Y directions (or positional deviation within the XY plane) of substrate P that is caused by bending of substrate P in the Z-axis direction because of the self weight, and so on, by supporting substrate P (in this case, an area excluding the portion subject to exposure of substrate P that is held by fixed-point stage 40 described previously) from below in a noncontact manner such that substrate P is maintained roughly parallel to a horizontal plane.

The plurality of air levitation units 50 are substantially the same air levitation units except that their placement positions are different. In the present embodiment, as shown in Fig. 2, for example, one each of air levitation unit 50 is placed on the +Y side and the -Y side of fixed-point stage 40, and two rows of air levitation unit rows, each of which is composed of, for example, eight air levitation units 50 disposed at an equal distance along the Y-axis direction, are placed at a predetermined distance along the X-axis direction on each of the +X side and the -X side of fixed-point stage 40. More specifically, the plurality of air levitation units 50 are placed so as to enclose the periphery of fixed-point stage 40. In the description below, the explanation is given assuming that the four rows of the air levitation unit rows are referred to as the first to fourth rows starting from the -X side for the sake for convenience,

and the eight air levitation units that configure each air levitation unit row are referred to as the first to eighth units starting from the -Y side for the sake for convenience.

As shown in Fig. 3, each of air levitation units 50 includes, for example, a main section 51 that jets a gas (e.g. air) to the lower surface of substrate P, a support section 52 that supports main section 51 from below, and a pair of leg sections 53 that support support section 52 from below on surface plate 12. Main section 51 is made up of a member having a rectangular parallelepiped shape and has a plurality of gas jetting ports on its upper surface (the surface on the +Z side). Main section 51 supports substrate P by levitation by jetting the gas (air) toward the lower surface of substrate P, and guides movement of substrate P when substrate P moves along the XY plane. The upper surface of each of the plurality of air levitation units 50 is located on the same XY plane. Incidentally, the air levitation unit can be configured such that the gas is supplied from a gas supplying device, which is not illustrated, arranged outside, or the air levitation unit itself can have a blower, e.g. a fan or the like. In this embodiment, as shown in Fig. 5(B), the pressure and the flow rate of the gas jetted from main section 51 are set such that a distance D_b (clearance) between the upper surface (air jetting surface) of main section 51 and the lower surface of substrate P is, for example, around 0.8 mm. Incidentally, the gas jetting ports can be formed by the mechanical processing or the main section is formed with a porous material and its holes can be used as the gas jetting ports.

Support section 52 is made up of a plate-shaped member

having a rectangular shape in a planar view, and its lower surface is supported by the pair of leg sections 53. Incidentally, the leg sections of a pair (two) of air levitation units 50 arranged on the +Y side and the -Y side of fixed-point stage 40, respectively, are configured so as not to come in contact with Y beam 33 (e.g. the leg sections are each formed into an inverse U-like shape and placed astride Y beam 33). Incidentally, the number and the placement of the plurality of the air levitation units are not limited to those described above as examples, and the number and the placement can appropriately be changed in accordance with, for example, the size, shape, weight and movable range of substrate P or the capability of each air levitation unit, or the like. Further, the shape of the support surface (gas jetting surface) of each of the air levitation units, the distance between the adjacent air levitation units and the like are also not limited in particular. The point is that the air levitation units should be placed so as to cover the entire area of a movable range where substrate P can move (or an area slightly larger than the movable range).

As shown in Fig. 2, substrate holding frame 60 has a rectangular outer shape (contour) with the X-axis direction serving as its longitudinal direction in a planar view, and is formed into a frame shape having the size in the thickness direction is small (thin) that has an opening section, in the center portion, having a rectangular shape in a planar view that penetrates in the Z-axis direction. Substrate holding frame 60 has a pair of X frame members 61x, each of which is a tabular member parallel to the XY plane with the X-axis

direction serving as its longitudinal direction, at a predetermined distance in the Y-axis direction, and the +X side ends of the pair of X frame members 61x are connected and the -X side ends of the pair of X frame members 61x are connected, respectively, by a Y frame member 61y that is a tabular member parallel to the XY plane with the Y-axis direction serving as its longitudinal direction. It is preferable from the viewpoint of securement of stiffness and reduction in weight that each of the pair of X frame members 61x and a pair of Y frame members 61y is formed with a material such as a fiber reinforcing synthetic resin material such as GFRP (Glass Fiber Reinforced Plastics) or ceramics.

On the upper surface of X frame member 61x on the -Y side, a Y movable mirror 62y having a reflection surface orthogonal to the Y-axis on its -Y side surface is fixed. And, on the upper surface of Y frame member 61y on the -X side, an X movable mirror 62x having a reflection surface orthogonal to the X-axis on its -X side surface is fixed. Positional information within the XY plane (including rotational information in the θ_z direction) of substrate holding frame 60 (i.e. substrate P) is constantly detected at a resolution of, for example, around 0.25 nm with a laser interferometer system that includes a plurality, e.g. two, of X laser interferometers 63x that irradiate the reflection surface of X movable mirror 62x with measurement beams and a plurality, e.g. two, of Y laser interferometers 63y that irradiate the reflection surface of Y movable mirror 62y with measurement beams. X laser interferometers 63x and Y laser interferometers 63y are fixed to body BD (not illustrated in Fig. 3, see Fig. 1) via

predetermined fixing members 64x and 64y, respectively.

Incidentally, the number of X laser interferometers 63x and the distance therebetween, and the number of Y laser interferometers 63y and the distance therebetween are set such
5 that the measurement beam from at least one interferometer of the respective interferometers is irradiated on the corresponding movable mirror within the movable range where substrate holding frame 60 is movable. Consequently, the number of the respective interferometers is not limited to
10 two, but for example, can be one, or three or more, depending on the movement stroke of the substrate holding frame.

Further, in the case of using a plurality of measurement beams, it is also possible that a plurality of optical systems are provided and the light source and the control unit are shared
15 by the plurality of measurement beams.

Substrate holding frame 60 has a plurality, e.g. four, of holding units 65 that hold the end (the outer peripheral portion) of substrate P by vacuum adsorption from below. Two each of the four holding units 65 are attached to the opposed
20 surfaces of the pair of X frame members 61x that are opposed to each other, so as to be spaced apart in the X-axis direction. Incidentally, the number and the placement of the holding units are not limited to those described above, but the extra holding unit(s) can be additionally arranged as needed, for example,
25 in accordance with the size and the vulnerability to bending of a substrate, and the like. Further, holding units 65 can be attached to the Y frame members.

As can be seen from Figs. 5(A) and 5(B), holding unit 65 has a hand 66 that is formed so as to have an L-like YZ

sectional shape. On the substrate mounting surface of hand 66, an adsorption pad 67 used to adsorb substrate P by, for example, vacuum adsorption is arranged. Further, on the upper end of hand 66, a joint member 68 is arranged, to which one end of a tube (the illustration is omitted) is connected while the other end of the tube is connected to a vacuum device that is not illustrated. Adsorption pad 67 and joint member 68 communicate with each other via a piping member arranged inside hand 66. On each of the surface of hand 66 and the surface of X frame member 61x that are opposed to each other, protrusion section 69a that protrudes is formed, and between the pair of protrusion sections 69a that are opposed to each other, a pair of plate springs 69 that are parallel to the XY plane and spaced apart in the Z-axis direction are installed via a plurality of bolts 69b. More specifically, hand 66 and X frame member 61x are connected by the parallel plate springs. Consequently, the position of hand 66 is restricted in the X-axis direction and the Y-axis direction with respect to X frame member 61x owing to the stiffness of plate springs 69, and on the other hand, regarding the Z-axis direction (vertical direction), hand 66 can be displaced in the Z-axis direction (can vertically move) without rotating in the θ_x direction owing to the elasticity of plate springs 69.

In this case, the lower end surface (-Z side end surface) of hand 66 protrudes on the -Z side, below the lower end surface (-Z side end surface) of each of the pair of the X frame members 61x and the pair of the Y frame members 61y. However, a thickness T of the substrate mounting surface of hand 66 is set less (e.g. set to around 0.5 mm) than distance D_b (e.g.

around 0.8 mm in the present embodiment) between the gas jetting surfaces of air levitation units 50 and the lower surface of substrate P. Therefore, a clearance of, for example, around 0.3 mm is formed between the lower surface of the substrate mounting surface of hand 66 and the upper surfaces of the plurality of air levitation units 50, and when substrate holding frame 60 moves parallel to the XY plane above the plurality of air levitation units 50, hand 66 and air levitation units 50 do not come in contact. Incidentally, as shown in Figs. 6(A) to 6(C), during an exposure operation of substrate P, hand 66 does not pass above fixed-point stage 40, and therefore, hand 66 and air chuck unit 80 do not come in contact as well. Incidentally, the substrate mounting surface section of hand 66 has a low stiffness in the Z-axis direction because the substrate mounting surface is thin as described above, but the area size of a portion that comes in contact with substrate P (flat portion parallel to the XY plane) can be large, and accordingly the adsorption pad can be increased in size, which improves the adsorption force of the substrate. Further, the stiffness of the hand itself in directions parallel to the XY plane can be secured.

As shown in Fig. 3, drive unit 70 has an X guide 71 fixed on surface plate 12, an X movable section 72 that is mounted on X guide 71 and is movable in the X-axis direction on X guide 71, a Y guide 73 mounted on X movable section 72, and a Y movable section 74 that is mounted on Y guide 73 and is movable in the Y-axis direction on Y guide 73. Y frame member 61y on the +X side of substrate holding frame 60 is fixed to Y movable section 74, as shown in Fig. 2.

As shown in Fig. 2, X guide 71 is placed on the -X side of fixed-point stage 40, between the fourth air levitation units 50 and the fifth air levitation units 50 that configure the third and the fourth air levitation unit rows. Further, X guide 71 extends on the +X side beyond the fourth air levitation unit row. Incidentally, in Fig. 3, from the viewpoint of preventing intricacy of the drawing, the illustration of air levitation units 50 is partially omitted. X guide 71 has a main section 71a made up of a plate-shaped member parallel to the XZ plane with the X-axis direction serving as its longitudinal direction and a plurality, e.g. three, of support tables 71b that support main section 71a on surface plate 12 (see Fig. 1). The position in the Z-axis direction of main section 71a is set such that the upper surface of main section 71a is located lower than the respective support sections 52 of the plurality of air levitation units 50.

On each of the side surface on the +Y side, the side surface on the -Y side and the upper surface (the surface on the +Z side) of main section 71a, as shown in Fig. 1, an X linear guide 75 arranged extending parallel to the X-axis direction is fixed. Further, on each of the side surface on the +Y side and the side surface on the -Y side of main section 71a, a magnetic unit 76 including a plurality of magnets disposed along the X-axis direction is fixed (see Fig. 3).

As shown in Fig. 1, X movable section 72 is made up of a member having an inverse U-like YZ sectional shape, and X guide 71 described earlier is inserted between a pair of opposed surfaces of the member. On each of the inner side

surfaces (the ceiling surface and the pair of opposed surfaces that are opposed to each other) of X movable section 72, a slider 77 formed so as to have a U-like sectional shape is fixed. Slider 77 has a rolling element (e.g. a ball, a skid or the like) that is not illustrated, and is engaged with (fitted into) X linear guide 75 in a slidable state with respect to X linear guide 75. Further, on each of the pair of opposed surfaces of X movable section 72, a coil unit 78 including coils is fixed so as to be opposed to magnetic unit 76 fixed to X guide 71. A pair of coil units 78 configure an X linear motor by the electromagnetic force drive method that drives X movable section 72 in the X-axis direction on X guide 71 owing to the electromagnetic interaction with a pair of magnetic units 76. The magnitude and the direction of the electric current supplied to the coils of coil units 78 are controlled by the main controller that is not illustrated. Positional information of X movable section 72 in the X-axis direction is measured by a linear encoder system or an optical interferometer system, which is not illustrated, with high precision.

On the upper surface of X movable section 72, one end (lower end) of a shaft 79 parallel to the Z-axis is fixed. As shown in Fig. 1, shaft 79 passes between the fourth air levitation unit 50 and the fifth air levitation unit 50 that configure the fourth air levitation unit row and extends on the +Z side beyond the upper surfaces (gas jetting surfaces) of the respective air levitation units 50. The other end (upper end) of shaft 79 is fixed to the center of the lower surface of Y guide 73 (see Fig. 3). Consequently, Y guide 73

is placed higher than the upper surfaces of air levitation units 50. Y guide 73 is made up of a plate-shaped member with the Y-axis direction serving as its longitudinal direction, and has a magnetic unit, which is not illustrated, including a plurality of magnets disposed along the Y-axis direction inside thereof. In this case, since Y guide 73 is placed above the plurality of air levitation units 50, the lower surface of Y guide 73 is supported by the air jetted from air levitation units 50, and accordingly, for example, the both ends of Y guide 73 in the Y-axis direction are prevented from bending downward because of the self weight. Consequently, the stiffness to prevent the downward bending referred to above needs not be secured, which allows reduction in weight of Y guide 73.

As shown in Fig. 3, Y movable section 74 is made up of a box-shaped member with a size in the height direction that is small (thin) having a space inside, and on the lower surface of Y movable section 74, an opening section that allows shaft 79 to pass through is formed. Further, Y movable section 74 has an opening section on the side surfaces on the +Y side and the -Y side as well, and Y guide 73 is inserted into Y movable section 74 via the opening sections. Further, Y movable section 74 has noncontact thrust bearings, which are not illustrated, e.g. air bearings, on the opposed surfaces opposed to Y guide 73, and Y movable section 74 is movable in the Y-axis direction above Y guide 73 in a noncontact state. Since substrate holding frame 60 to hold substrate P is fixed to Y movable section 74, substrate holding frame 60 is in a noncontact state with respect to fixed-point stage 40

described previously and each of the plurality of air levitation units 50.

Furthermore, Y movable section 74 has a coil unit including coils (the illustration is omitted) inside thereof.

5 The coil unit configures a Y linear motor by the electromagnetic force drive method that drives Y movable section 74 in the Y-axis direction above Y guide 73 owing to the electromagnetic interaction with the magnetic unit that Y guide 73 has. The magnitude and the direction of the electric

10 current supplied to the coils of the coil unit are controlled by the main controller that is not illustrated. Positional information of Y movable section 74 in the Y-axis direction is measured by a linear encoder system or an optical interferometer system, which is not illustrated, with high

15 precision. Incidentally, each of the X linear motor and the Y linear motor described above is either of the moving magnet type or the moving coil type, and the drive method is not limited to the Lorentz force drive method but can be other methods such as a variable magnetoresistance drive method.

20 Further, as a drive device that drives the X movable section described above in the X-axis direction and a drive device that drives the Y movable section described above in the Y-axis direction, for example, a uniaxial drive device can be used that includes a ball screw, a rack-and-pinion or the like,

25 or a device can be used that drives the X movable section and the Y movable section in the X-axis direction and the Y-axis direction, respectively, by towing the X movable section and the Y movable section using a wire, a belt or the like, for example, according to the required accuracy of positioning

of substrates, the throughput, the movement stroke of substrates, and the like.

Besides, liquid crystal exposure apparatus 10 has a surface position measuring system (the illustration is omitted) that measures surface position information (positional information in each of the Z-axis, θ_x and θ_y directions) of the surface (upper surface) of substrate P located directly under projection optical system PL. As the surface position measuring system, the one by an oblique incidence method as disclosed in, for example, U.S. Patent No. 5,448,332 and the like can be used.

In liquid crystal exposure apparatus 10 (see Fig. 1) configured as described above, under control of the main controller that is not illustrated, mask M is loaded onto mask stage MST by a mask loader that is not illustrated and substrate P is loaded onto substrate stage device PST by a substrate loader that is not illustrated. After that, the main controller executes alignment measurement using an alignment detection system that is not illustrated, and after the alignment measurement is completed, performs an exposure operation by a step-and-scan method.

Figs. 6(A) to 6(C) show an example of an operation of substrate stage device PST during the exposure operation referred to above. Note that in the description below, the case of so-called two displays on a single substrate is described where one each of a rectangular shot area whose longitudinal direction is in the X-axis direction is set in an area on the +Y side and an area on the -Y side of substrate P. As shown in Fig. 6(A), the exposure operation is performed

from an area on the -Y side located on the -X side of substrate P toward an area on the -Y side located on the +X side of substrate P. On this operation, X movable section 72 (see the drawings such as Fig. 1) of drive unit 70 is driven in the -X direction on X guide 71, and thereby substrate P is driven in the -X direction (see a black arrow in Fig. 6(A)) with respect to exposure area IA and a scan operation (exposure operation) is performed on an area on the -Y side of substrate P. Subsequently, on substrate stage device PST, as shown in Fig. 6(B), Y movable section 74 of drive unit 70 is driven in the -Y direction (see a white arrow in Fig. 6(B)) above Y guide 73, and thereby a step operation is performed. After that, as shown in Fig. 6(C), X movable section 72 (see the drawings such as Fig. 1) of drive unit 70 is driven in the +X direction on X guide 71, and thereby substrate P is driven in the +X direction (see a black arrow in Fig. 6(C)) with respect to exposure area IA and a scan operation (exposure operation) is performed on an area on the +Y side of substrate P.

In the middle of the exposure operation by a step-and-scan method shown in Figs. 6(A) to 6(C), the main controller constantly measures positional information of substrate P within the XY plane and surface position information of a portion subject to exposure of the substrate P surface using the interferometer system and the surface position measuring system, and appropriately controls the four Z-VCMS based on the measurement values, thereby adjusting (positioning) the surface position (the position in the Z-axis direction and each of the θ_x and θ_y directions) of a section

held by fixed-point stage 40, or more specifically, the surface position of the portion subject to exposure that is located directly under projection optical system PL such that the surface position is located within a depth of focus of projection optical system PL. Accordingly, in substrate stage device PST that liquid crystal exposure apparatus 10 of the present embodiment has, for example, even if the surface of substrate P has undulation or substrate P has error in thickness, the surface position of the portion subject to exposure of substrate P can surely be located within a depth of focus of projection optical system PL, which makes it possible to improve the exposure accuracy.

Further, when the surface position of substrate P is adjusted by fixed-point stage 40, hand 66 of substrate holding frame 60 is displaced in the Z-axis direction, following the operation (a movement in the Z-axis direction or a tilt operation) of substrate P. Accordingly, damage of substrate P, a shift (adsorption error) between hand 66 and substrate P, or the like is prevented. Incidentally, since the plurality of air levitation units 50 levitate substrate P higher compared with air chuck unit 80, the air stiffness between substrate P and the plurality of air levitation units 50 is lower compared with the air stiffness between air chuck unit 80 and substrate P. Consequently, substrate P can change its attitude without difficulty above the plurality of air levitation units 50. Further, if the amount of the attitude change of substrate P is large and hand 66 cannot follow substrate P, the adsorption error referred to above or the like can be avoided by the attitude of substrate holding frame

60 itself changing, since Y movable section 74 to which substrate holding frame 60 is fixed is supported by Y guide 73 in a noncontact manner. Incidentally, a configuration can also be employed in which the stiffness of the fastening section between Y guide 73 and X movable section 72 is lowered and the attitude of the entire Y guide 73 changes together with substrate holding frame 60.

Further, in substrate stage device PST, substrate P that is substantially horizontally supported by levitation with the plurality of air levitation units 50 is held by substrate holding frame 60. Then, in substrate stage device PST, substrate holding frame 60 is driven by drive unit 70, and thereby substrate P is guided along a horizontal plane (the XY two-dimensional plane) and also the surface position of the portion subject to exposure of substrate P (a part of substrate P, within exposure area IA) is controlled by fixed-point stage 40 in a pinpoint manner. As described above, in substrate stage device PST, drive unit 70 (XY stage device) that is a device to guide substrate P along the XY plane, and the plurality of air levitation units 50 and fixed-point stage 40 (Z/leveling stage device) that are devices to hold substrate P substantially horizontally and to position substrate P in the Z-axis direction are of different bodies that are independent from each other, and therefore, the weight of substrate stage device PST (especially, the weight of its movable section) can be considerably reduced, compared with a conventional stage device (e.g. refer to PCT International Publication No. 2008/129762 (the corresponding U.S. Patent Application Publication No. 2010/0018950)) that drives a

table member (substrate holder) used to hold substrate P with a good flatness degree, having an area size that is around the same as an area size of substrate P, in the Z-axis direction and the tilt direction respectively (the Z/leveling stage is also driven XY-two-dimensionally together with the substrate), on an XY two-dimensional stage device. To be specific, for example, in the case of using a large substrate one side of which exceeds 3 m, the total weight of the movable section amounts to nearly 10 t in the conventional stage device, whereas the total weight of the movable section (such as substrate holding frame 60, X movable section 72, Y guide 73 and Y movable section 74) can be reduced to around several hundreds kg in substrate stage device PST of the present embodiment. Consequently, for example, each of the X linear motor used to drive X movable section 72 and the Y linear motor used to drive Y movable section 74 can be the linear motor with small outputs, which makes it possible to reduce the running cost. Further, the infrastructure such as power-supply facility can be provided without difficulty. Further, the initial cost can also be reduced because the outputs of the linear motors can be small.

Further, in drive unit 70, Y movable section 74 that holds substrate holding frame 60 is supported by Y guide 73 in a noncontact manner, and substrate P is guided along the XY plane, and therefore, there is little risk that the vibration (disturbance) in the Z-axis direction transmitted via the air bearings from the side of surface plate 12 installed on floor surface F adversely affects control of substrate holding frame 60. Consequently, the attitude of substrate P

becomes stable and the exposure accuracy is improved.

Further, Y movable section 74 of drive unit 70 is supported by Y guide 73 in a noncontact state and dust is prevented from being generated, and therefore, although Y guide 73 and Y movable section 74 are placed above the upper surfaces (gas jetting surfaces) of the plurality of air levitation units 50, the exposure processing of substrate P is not affected. Meanwhile, X guide 71 and X movable section 72 are placed below air levitation units 50, and therefore, even if dust is generated, the possibility that dust affects the exposure processing is low. However, X movable section 72 can be supported in a noncontact state with respect to X guide 71 so as to be movable in the X-axis direction, using, for example, air bearings or the like.

Further, weight canceller 42 of fixed-point stage 40 and air chuck unit 80 are mounted on Y beam 33 that is separated from surface plate 12 in terms of vibration, and therefore, for example, the reaction force of the drive force, vibration, or the like that is generated when substrate holding frame 60 (substrate P) is driven using drive unit 70 is not transmitted to weight canceller 42 and air chuck unit 80. Consequently, control of the position of air chuck unit 80 (i.e. the surface position of the portion subject to exposure of substrate P) using the Z-VCMS can be performed with high precision. Further, of the four Z-VCMS that drive air chuck unit 80, Z stators 47 are fixed to base frame 85 that is noncontact with Y beam 33, and therefore the reaction force of the drive force generated when air chuck unit 80 is driven is not transmitted to weight canceller 42. Consequently, the

position of air chuck unit 80 can be controlled with high precision.

Further, positional information of substrate holding frame 60 is measured with the interferometer system that uses
5 movable mirrors 62x and 62y that are fixed to substrate frame 60, or more specifically, are placed close to substrate P that is subject to final positioning control, and therefore, the stiffness between the control subject (substrate P) and the measurement points can be maintained high. More specifically,
10 since the substrate whose final position should be known and the measurement points can be regarded as being integrated, the measurement accuracy is improved. Further, the positional information of substrate holding frame 60 is directly measured, and therefore, even if a linear motion error
15 occurs in X movable section 72 and Y movable section 74, the measurement results are hard to be affected.

Further, the size in the X-axis direction of the upper surface (substrate holding surface) of main section 81 of air
chuck unit 80 is set longer than the size in the X-axis
20 direction of exposure area IA, and therefore, in a state where a portion subject to exposure (a portion to be exposed) of substrate P is located upstream of exposure area IA in the movement direction of substrate P, especially just before starting scanning exposure, the surface position of the
25 portion subject to exposure of substrate P can be adjusted in advance, at an acceleration stage before performing constant-velocity movement of substrate P. Consequently, the surface position of the portion subject to exposure of substrate P can surely be located within a depth of focus of

projection optical system PL from the beginning of exposure, and accordingly the exposure accuracy can be improved.

Further, in substrate stage device PST, a configuration is employed in which the plurality of air levitation units 5 50, fixed-point stage 40 and drive unit 70 are placed side by side in a planar manner on surface plate 12, and therefore, the assembly, adjustment, maintenance and the like can be performed without difficulty. Further, the members are small in number and also the respective members are lightweight, 10 which facilitates the transportation as well.

Incidentally, for example, in the cases such as when the +X side end or the -X side end of substrate P passes above fixed-point stage 40, a state where substrate P overlaps only a part of air chuck unit 80 (a state where air chuck unit 80 15 is not completely covered with substrate P) is created. In such a case, since the load of substrate P acting on the upper surface of air chuck unit 80 is decreased, the force of air chuck unit 80 that levitates substrate P is weakened because of imbalance of the air, and distance D_a (see Fig. 5(B)) between 20 air chuck unit 80 and substrate P becomes smaller than a desired value (e.g. 0.02 mm). In this case, the main controller controls the air pressure and/or the air flow rate between air chuck unit 80 and the lower surface of substrate P (the pressure and/or the flow rate of the air that main section 25 81 jets and suction) in accordance with the position of substrate P (in accordance with the overlapping area size of substrate P and the holding surface) such that distance D_a between the upper surface of air chuck unit 80 and the lower surface of substrate P is maintained at a constant desired

value at all times. It is preferable that to what level the pressure and/or the flow rate of the air should be set in accordance with the position of substrate P is obtained in advance by experiments. Further, it is also possible that the upper surface of air chuck unit 80 is divided into a plurality of areas along the X-axis direction and the flow rate and/or the pressure of air that is jetted and suctioned can be controlled for each of the divided areas. Further, the distance between the upper surface of air chuck unit 80 and the lower surface of substrate P can appropriately be adjusted by vertically moving air chuck unit 80 in accordance with the positional relation between substrate P and air chuck unit 80 (the overlapping area size of substrate P and the holding surface).

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- Second Embodiment

Next, a liquid crystal exposure apparatus of a second embodiment is described. Since the liquid crystal exposure apparatus of the present second embodiment has a configuration similar to the configuration of liquid crystal exposure apparatus 10 of the first embodiment described earlier except that a configuration of a substrate stage device that holds substrate P is different, only the configuration of the substrate stage device is explained in the description below. Herein, from the viewpoint of preventing the redundant description, members which have functions equivalent to those of the first embodiment are denoted by the same reference signs as the reference signs in the first embodiment and the description thereabout is omitted.

As shown in Fig. 7(A), in a substrate stage device PST_2 related to the second embodiment, a configuration of a substrate holding frame 260 is different from the first embodiment. The different points are explained below.

5 Similarly to the first embodiment, substrate holding frame 260 is formed into a rectangular frame shape that encloses substrate P, and has a pair of X frame members 261x and a pair of Y frame members 261y. Incidentally, in Fig. 7(A), the illustration of an X movable mirror and a Y movable mirror
10 is omitted (see Fig. 2 for each of them).

Substrate holding frame 60 (see Fig. 5(A)) of the first embodiment holds substrate P by adsorption from below with the hand having an L-like sectional shape, whereas in the case of substrate holding frame 260 of the second embodiment, a
15 pair of pressing members 264 attached to Y frame member 261y on the -X side via compression coil springs 263 and one pressing member 264 attached to X frame member 261x on the +Y side via a compression coil spring 263 press substrate P against a pair of reference members 266 fixed to Y frame member 261y on the
20 +X side and one reference member 266 fixed to X frame member 261x on the -Y side, respectively, (make the pressing forces parallel to the XY plane act on substrate P), and thereby substrate holding frame 260 holds substrate P. Consequently, different from the first embodiment, substrate P is housed
25 within an opening of substrate holding frame 260 that is a frame-shaped member (see Fig. 7(B)). As shown in Fig. 7(B), substrate P is placed such that its lower surface is placed so as to be substantially coplanar with the lower surface of substrate holding frame 260. Incidentally, the number of the

pressing members and the reference members can appropriately be changed in accordance with, for example, the size of the substrate or the like. Further, the pressing member that presses the substrate is not limited to the compression coil spring but can be an air cylinder or a slide unit that uses a motor.

Further, in substrate stage device PST₂ related to the second embodiment, as shown in Fig. 7(B), a pair of Y linear guides 90, placed at a predetermined distance in the X-axis direction, are fixed to the upper surface of a Y guide 273 that is a tabular member fixed to X movable section 72 via shaft 79. Further, between the pair of Y linear guides 90, a magnetic unit 91 including a plurality of magnets disposed along the Y-axis direction is fixed. Meanwhile, Y movable section 274 is made up of a tabular member parallel to the XY plane, and on the lower surface of Y movable section 274, a plurality, e.g. four, of sliders 92 each of which is formed so as to have an inverse U-like sectional shape are fixed (see Fig. 7(B), of the four sliders 92, the illustration of the two on the +Y side is omitted). The four sliders 92 each have a rolling element (e.g. a ball, a skid or the like) which is not illustrated, and two each of sliders 92 are engaged with Y linear guide 90 on the +X side and Y linear guide 90 on the -X side in a slidable state with respect to the corresponding Y linear guide 90, respectively. Further, on the lower surface of Y movable section 274, a coil unit 93 (see Fig. 7(B)) including coils is fixed so as to be opposed to magnetic unit 91 fixed to Y guide 273. Coil unit 93 and magnetic unit 91 configure a Y linear motor by the electromagnetic force

drive method that drives Y movable section 274 in the Y-axis direction on Y guide 273 owing to the electromagnetic interaction. Incidentally, the placement of the coil unit and the magnetic unit that configure the Y linear motor can be reverse to the above-described placement.

Further, in the second embodiment, Y movable section 274 and substrate holding frame 260 are connected by a hinge device 299. While hinge device 299 restricts relative movement of Y movable section 274 and substrate holding frame 260 along a horizontal plane (XY plane), hinge device 299 allows relative movement in directions around predetermined axis lines parallel to the XY plane including the θ_x direction and the θ_y direction. Consequently, Y movable section 274 and substrate holding frame 260 integrally move along the XY plane, but in the case where substrate P is tilted with respect to XY plane by fixed-point stage 40, only substrate holding frame 260 is tilted with respect to the XY plane following the tilt of substrate P, and therefore the load is not placed on Y linear guide 90 and slider 92.

Since substrate holding frame 260 of substrate stage device PST₂ related to the second embodiment as described above has no protrusions, including substrate P, which protrude below the lower surfaces of X frame members 261x and Y frame members 261y, it is possible to make the lower surface of substrate holding frame 260 and the upper surfaces (gas jetting surfaces) of the plurality of air levitation units 50 come close together compared with the first embodiment. Accordingly, the height of levitation of substrate P by air levitation units 50 can be lowered, which allows the flow rate

of the air jetted from air levitation units 50 to be reduced. Consequently, the running cost can be decreased. Further, since substrate holding frame 260 has no protrusions on its lower surface, the pair of X frame members 261x and the pair of Y frame members 261y can pass above air chuck unit 80 respectively. Consequently, the movement course of substrate P used when substrate P is guided to, for example, a substrate exchange position that is not illustrated, an alignment measurement position or the like can be freely set.

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- Third Embodiment

Next, a third embodiment is described. Since a liquid crystal exposure apparatus of the third embodiment has a configuration similar to the configuration of each of the liquid crystal exposure apparatuses of the first and second embodiments described earlier except that a configuration of a substrate stage device that holds substrate P is different, only the configuration of the substrate stage device is described below. Incidentally, members which have functions similar to those in the first and second embodiments described above are denoted by the same reference signs as the reference signs in the first and second embodiments described above and the description thereabout is omitted.

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As shown in Fig. 8, in a substrate stage device PST₃ related to the present third embodiment, a drive unit 370 has a pair of X guides 71, which is different from the first embodiment described above. The pair of X guides 71 are placed parallel to each other at a predetermined distance in the Y-axis direction. One (on the -Y side) of the pair of X guides

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71 is placed between the second air levitation units 50 and the third air levitation units 50 that configure the third and fourth air levitation unit rows, and the other (on the +Y side) is placed between the sixth air levitation units 50 and the seventh air levitation units 50. On each of the pair of X guides 71, X movable section 72 (X movable section 72 is not illustrated in Fig. 8, see Figs. 1 and 3) is mounted. A pair of X movable sections 72 are synchronously driven on the respective corresponding X guides 71 by the main controller that is not illustrated. Further, Y guide 73 is installed over the pair of X movable sections 72 by being supported on the pair of X movable sections 72 via shaft 79 (shaft 79 is not illustrated in Fig. 8, see Figs. 1 and 3), similarly to the first embodiment.

In substrate stage device PST₃ related to the third embodiment, Y guide 73 is supported, at two points that are apart in the Y-axis direction, by X movable sections 72, and therefore, for example, in the case where Y movable section 74 is located near the +Y side end or the -Y side end on Y guide 73, the downward bending of one of the ends of Y guide 73 is restrained and so on, which allows the attitude of Y guide 73 to be stable. Thus, this is especially effective in the cases such as when the length of Y guide 73 is increased in order to guide substrate P with a long stroke in the Y-axis direction.

Incidentally, in substrate stage device PST₃ of the third embodiment, one of X guides 71 is placed on the -Y side of fixed-point stage 40 and the other of X guides 71 is placed on the +Y side of fixed-point stage 40, and therefore, each

of the pair of X guides 71 can be arranged extending to the vicinity of the -X side end of surface plate 12 (in this case, the pair of X guides 71 are configured so as not to come in contact with Y beam 33 and each of air levitation units 50 on the +Y side and the -Y side of fixed-point stage 40). In such a case, it becomes possible to guide substrate holding frame 60 to the -X side beyond fixed-point stage 40 (e.g. it is also possible to guide substrate holding frame 60 to the -X side beyond the -X side end of surface plate 12). Since the movable range where substrate P is movable within the XY plane can be increased in this manner, it is possible to move substrate P to a position (e.g. the substrate exchange position, the alignment measurement position, or the like) different from the exposure position using drive unit 370. Incidentally, while the pair (two) of X guides 71 are arranged in the present third embodiment, the number of the X guides is not limited thereto, but can be three or more.

- Fourth Embodiment

Next, a fourth embodiment is described with reference to Figs. 9 and 10. Since a liquid crystal exposure apparatus of the fourth embodiment has a configuration similar to the configuration of each of the liquid crystal exposure apparatuses of the first, second and third embodiments except that a configuration of a substrate stage device is different, only the configuration of the substrate stage device is described below. Incidentally, members which have functions similar to those in the first to third embodiments described above are denoted by the same reference signs as the reference

signs in the first to third embodiments described above and the description thereabout is omitted.

As shown in Fig. 9, a substrate holding frame 460 of a substrate stage device PST₄ related to the present fourth embodiment is formed into a frame shape made up of a pair of X frame members 61x with the X-axis direction serving as their longitudinal directions and a pair of Y frame members 61y with the Y-axis direction serving as their longitudinal directions. And, an X movable mirror 462x is fixed to the side surface on the -X side (outer side surface) of Y frame member 61y on the -X side and a Y movable mirror 462y is fixed to the side surface on the -Y side (outer side surface) of X frame member 61x on the -Y side. X movable mirror 462x and Y movable mirror 462y are used when the interferometer system measures positional information of substrate holding frame 460 within the XY plane. Incidentally, in the case where each of the pair of X frame members 61x and the pair of Y frame members 61y is formed with, for example, ceramics, the side surface on the -X side (outer side surface) of Y frame member 61y on the -X side and the side surface on the -Y side (outer side surface) of X frame member 61x on the -Y side can respectively be mirror-polished to serve as reflection surfaces.

In a drive unit 470, Y guide 73 is installed over a pair of X movable sections 72, which is similar to substrate stage device PST₃ (see Fig. 8) of the third embodiment described above. And, as shown in Fig. 9, above Y guide 73, a pair of Y movable sections 474 are each supported in a noncontact state so as to be movable in the Y-axis direction with a Y linear motor (the illustration is omitted). The pair of Y movable sections

474 are placed at a predetermined distance in the Y-axis direction, and are driven in synchronization by the Y linear motors. Incidentally, although Y movable section 474 on the +Y side is hidden behind Y movable section 474 on the -Y side in a direction of the depth of the page surface in Fig. 10, the pair of Y movable sections 474 have substantially the same configuration (see Fig. 9). In substrate holding frame 460, Y frame member 61y on the +X side is fastened with the pair of Y movable sections 474.

10 In substrate stage device PST_4 related to the fourth embodiment as described above, substrate holding frame 460 is supported, at two points that are apart in the Y-axis direction, by the pair of Y movable sections 474, and therefore, the bending (especially, bending of the ends on the +Y side and on the -Y side) owing to the self weight can be restrained. Further, with this configuration, the stiffness of substrate holding frame 460 in a direction parallel to a horizontal plane is improved, and therefore, the stiffness of substrate P, which is held by substrate holding frame 460, in a direction parallel to a horizontal plane is also improved, which improves the positioning accuracy of substrate P.

25 Further, on the side surfaces of X frame member 61x and Y frame member 61y that configure substrate holding frame 460, movable mirrors 462x and 462y are respectively arranged, or more specifically, substrate holding frame 460 itself has the reflection surfaces, and therefore, the weight and the size of substrate holding frame 460 can be reduced, which improves the position controllability of substrate holding frame 460. Further, the positions in the Z-axis direction of the

reflection surfaces of movable mirrors 462x and 462y come close to the position of the surface of substrate P in the Z-axis direction, and therefore, occurrence of the so-called Abbe error can be restrained, which improves the positioning accuracy of substrate P.

- Fifth Embodiment

Next, a fifth embodiment is described with reference to Figs. 11 and 12. Since a liquid crystal exposure apparatus of the fifth embodiment has a configuration similar to the configuration of each of the liquid crystal exposure apparatuses of the first to fourth embodiments except that a configuration of a substrate stage device is different, only the configuration of the substrate stage device is described below. Incidentally, members which have functions similar to those in the first to fourth embodiments described above are denoted by the same reference signs as the reference signs in the first to fourth embodiments described above and the description thereabout is omitted.

As shown in Fig. 11, in a substrate stage device PST₅ related to the fifth embodiment, one Y movable section 574 is supported by Y guide 73 in a noncontact state so as to be movable in the Y-axis direction by a Y linear motor (the illustration is omitted). Further, as shown in Fig. 12, Y movable section 574 has, on the side surface on the -X side, a pair of holding members 591 each of which is made up of a member formed so as to have a U-like XZ sectional shape. The pair of holding members 591 are placed at a predetermined distance along the Y-axis direction. Each of the pair of

holding members 591 has noncontact thrust bearings, e.g. air bearings or the like, on a pair of opposed surfaces that are opposed to each other. Further, substrate holding frame 560 has a Y frame member 561y on the +X side that is formed so as to have an L-like XZ sectional shape and the +X side end of Y frame member 561y is inserted between the pair of opposed surfaces of each of the pair of holding members 591, and thereby substrate holding frame 560 is held by Y movable section 574 in a noncontact manner. Incidentally, as the noncontact thrust bearings arranged on the pair of holding members 591, for example, magnetic bearings or the like can be used.

As shown in Fig. 11, on the upper surface of Y movable section 574, one Y stator 576y and a pair of X stators 576x are fixed via a fixing member 575. Y stator 576y is located between the pair of holding members 591 in a planar view. The pair of X stators 576x are apart in the Y-axis direction and are located on the +Y side of holding member 591 on the +Y side and on the -Y side of holding member 591 on the -Y side, respectively, in a planar view. Y stator 576y and the pair of X stators 576x each have a coil unit including coils (the illustration is omitted). The magnitude and the direction of the electric current supplied to the coils of the coil units are controlled by the main controller that is not illustrated.

Further, on the upper surface of Y frame member 561y on the +X side of substrate holding frame 560, one Y mover 577y and a pair of X movers 577x are each fixed via a fixing member 578 (see Fig. 12, the illustration of the fixing members that support the pair of Y movers 577x respectively is omitted), so as to correspond to Y stator 576y and the pair of X stators

576x described above. Each of the one Y mover 577y and the pair of X movers 577x is formed so as to have a U-like XZ sectional shape and has a pair of opposed surfaces that are opposed to each other between which the corresponding Y stator 576y or X stator 576x is inserted (see Fig. 12). The one Y mover 577y and the pair of X movers 577x each have a magnetic unit 579 including magnets on a pair of opposed surfaces that are opposed to each other (see Fig. 12, the illustration of the magnetic units of the pair of X movers 577x is omitted).

10 Magnetic unit 579, which Y mover 577y has, configures a Y voice coil motor (Y-VCM) by the electromagnetic force drive method that finely drives substrate holding frame 560 in the Y-axis direction (see an arrow in Fig. 11) owing to the electromagnetic interaction with the coil unit that Y stator 576y has. Further, the magnetic units, which the pair of X movers 577x have, configure a pair of X voice coil motors (X-VCMs) by the electromagnetic force drive method that finely drive substrate holding frame 560 in the X-axis direction (see arrows in Fig. 11) owing to the electromagnetic interaction with the respectively corresponding coil units that X stators 576x have. Substrate holding frame 560 and Y movable section 574 are electromagnetically coupled in a noncontact state by the electromagnetic forces generated by the Y-VCM and the pair of X-VCMs, and integrally move along the XY plane.

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25 Incidentally, on the side surfaces of substrate holding frame 560, X movable mirror 462x and Y movable mirror 462y are fixed respectively, which is similar to the fourth embodiment described above.

In substrate stage device PST₅ related to the fifth

embodiment, for example, during an exposure operation or the like, the main controller controls the positions of X movable section 72 and Y movable section 574 using the X linear motor and the Y linear motor based on the measurement values of a linear encoder system that is not illustrated, thereby performing the rough positioning of substrate holding frame 570 (substrate P) within the XY plane, and also finely drives substrate holding frame 570 along the XY plane by appropriately controlling the Y-VCM and the pair of X-VCMs based on the measurement values of the interferometer system, thereby performing the final positioning of substrate P within the XY plane. On this operation, the main controller drives substrate holding frame 560 also in the θ_z direction by appropriately controlling the outputs of the pair of X-VCMs. More specifically, in substrate stage device PST₅, an XY two-dimensional stage device composed of the pair of X guides 71, X movable section 72, Y guide 73 and Y movable section 574 functions as a so-called coarse movement stage device, and substrate holding frame 560 that is finely driven by the Y-VCM and the pair of X-VCMs with respect to Y movable section 574 functions as a so-called fine movement stage device.

As described above, according to substrate stage device PST₅ related to the fifth embodiment, since the positioning of substrate P within the XY plane can be performed with high precision with respect to Y movable section 574 using substrate holding frame 570 that is lightweight, the positioning accuracy and the positioning speed of substrate P are improved. On the other hand, since the nano-order accuracy is not required for the positioning accuracy of X movable section

72 by the X linear motor and the positioning accuracy of Y
movable section 574 by the Y linear motor, an inexpensive
linear motor and an inexpensive linear encoder system can be
used. Further, since substrate holding frame 560 and Y
5 movable section 574 are separated in terms of vibration, the
vibration in a horizontal direction and the reaction forces
of the drive forces of the X-VCMs and the Y-VCM do not travel
to substrate holding frame 560.

10 - Sixth Embodiment

Next, a sixth embodiment is described with reference to
Fig. 13. Since a liquid crystal exposure apparatus of the
sixth embodiment has a configuration similar to the
configuration of each of the liquid crystal exposure
15 apparatuses of the first to fifth embodiments except that a
configuration of a substrate stage device is different, only
the configuration of the substrate stage device is described
below. Incidentally, members which have functions similar to
those in the first to fifth embodiments described above are
20 denoted by the same reference signs as the reference signs
in the first to fifth embodiments described above and the
description thereabout is omitted.

As shown in Fig. 13, a drive unit 670 of a substrate stage
device PST₆ related to the six embodiment has an XY
25 two-dimensional stage device having a configuration similar
to that of the fifth embodiment described above, in an area
on the +X side of fixed-point stage 40. More specifically,
the XY two-dimensional stage, which is composed of a pair of
X guides 71 fixed on surface plate 12, a pair of X movable

sections 72 (not illustrated in Fig. 13, see Fig. 12) that move in the X-axis direction on the pair of X guides 71, a Y guide 73 installed over the pair of X movable sections 72, and a Y drive section 574 (which is referred to as a first Y movable section 574, for the sake of convenience) that moves in the Y-axis direction on Y guide 73, is arranged in the area on the +X side of fixed-point stage 40. The first Y movable section 574 has a pair of holding members 591 that hold, in a noncontact manner, a substrate holding frame 660 that has a configuration similar to that of the fifth embodiment described above. Further, substrate holding frame 660 is finely driven in the X-axis direction, the Y-axis direction and the θ_z direction with respect to the first Y movable section 574, by three voice coil motors (one Y-VCM and a pair of X-VCMs) that are configured of a Y stator and a pair of X stators fixed to Y movable section 574 that has a configuration similar to the fifth embodiment described above and a Y mover and a pair of X movers fixed to a Y frame member 661y on the +X side of substrate holding frame 660.

Substrate stage device PST_6 further has another XY two-dimensional stage device, in an area on the -X side of fixed-point stage 40, which has a configuration similar to the XY two-dimensional stage device described earlier (however, symmetric with respect to Y-axis (bilateral symmetric on the page surface)), or more specifically, which is composed of a pair of X guides 71, a pair of X movable sections 72 (not illustrated in Fig. 13, see Fig. 12), Y guide 73 and Y movable section 574 (which is referred to as a second Y movable section 574 for the sake of convenience). Substrate

holding frame 660 has Y frame member 661y on the -X side that is also formed so as to have an L-like sectional shape (see Fig. 12), which is similar to Y frame member 661y on the +X side, and Y frame member 661y on the -X side is held, in a noncontact manner, by a pair of holding members 591 that the second Y movable section 574 has.

Further, substrate holding frame 660 is finely driven in the X-axis direction, the Y-axis direction and the θ_z direction with respect to the second Y movable section 574, by three voice coil motors (one Y-VCM and a pair of X-VCMS) that are configured of a Y stator and a pair of X stators fixed to the second Y movable section 574, and a Y mover and a pair of X movers fixed to Y frame member 661y on the -X side of substrate holding frame 660. The main controller, which is not illustrated, coarsely adjusts the position of substrate holding frame 660 within the XY plane by synchronously controlling the X linear motors and the Y linear motor on each of the +X side and the -X side of fixed-point stage 40 based on the measurement values of a linear encoder system that is not illustrated, and also finely adjusts the position of substrate holding frame 660 (substrate P) within the XY plane by appropriately controlling the Y-VCM and the pair of the X-VCMS on each of the +X side and the -X side of substrate holding frame 660 (substrate P) based on the measurement values of an interferometer system to finely drive the substrate holding frame in each of the X-axis, Y-axis and θ_z directions.

In substrate stage device PST₆ related to the sixth embodiment, since both ends of substrate holding frame 660 in the X-axis direction are supported by the XY two-dimensional

stage devices, the bending (downward bending on the free end side) owing to the self weight of substrate holding frame 660 is restrained. Further, since the drive forces by the voice coil motors are made to act on substrate holding frame 660 from the +X side and the -X side, respectively, it is possible to make the drive forces of the respective voice coil motors act on the vicinity of the position of the center of gravity of a system that is composed of substrate holding frame 660 and substrate P. Consequently, the moment in the θ_z direction can be restrained from acting on substrate holding frame 660. Incidentally, it is also possible that, only one each of the X-VCM is placed on the -X side and the +X side of substrate holding frame 660, at diagonal positions (such that the center of the diagonal line is located in the vicinity of the center of gravity of substrate P) such that the X-VCMs drive the position of the center of gravity of substrate holding frame 660.

- Seventh Embodiment

Next, a seventh embodiment is described with reference to Figs. 14 and 15. Since a liquid crystal exposure apparatus of the seventh embodiment has a configuration similar to the configuration of each of the liquid crystal exposure apparatuses of the first to sixth embodiments except that a configuration of a substrate stage device is different, only the configuration of the substrate stage device is described below. Incidentally, members which have functions similar to those in the first to sixth embodiments described above are denoted by the same reference signs as the reference signs

in the first to sixth embodiments described above and the description thereof is omitted.

As shown in Fig. 14, a substrate stage device PST₇ is different from the substrate stage device related to each of the first to sixth embodiments described above, in a configuration of a drive unit 770 that drives a substrate holding frame 760 along the XY two-dimensional plane. In substrate stage device PST₇, a pair of Y guides 771 with the Y-axis direction serving as their longitudinal directions are placed at a predetermined distance in the Y-axis direction, between the first air levitation unit row and the second air levitation unit row, and between the third air levitation unit row and the fourth air levitation unit row. These four Y guides 771 have functions similar to those of X guides 71 (see Fig. 3) that the substrate stage device related to each of the first to sixth embodiments described above has. Further, as shown in Fig. 15, on each of the four Y guides 771, a Y movable section 772 is mounted (the illustration of the two Y movable sections 772 on the -X side is omitted) that has functions similar to those of X movable section 72 (see Fig. 3) that the substrate stage device related to each of the first to sixth embodiments described above has. The four Y movable sections 772 are synchronously driven in the Y-axis direction by a Y linear motor by the electromagnetic force drive method that is composed of Y stators 776 (see Fig. 15) that Y guides 771 respectively have and Y movers (the illustration is omitted) that Y movable sections 772 respectively have.

Between the two Y movable sections 772 on the +Y side, as shown in Fig. 14, an X guide 773 made up of a tabular member

with the X-axis direction serving as its longitudinal direction is installed via a shaft 779 (see Fig. 15). And, between the two Y movable sections 772 on the -Y side as well, a similar X guide 773 is installed. On each of a pair of X guides 773, an X movable section 774 is mounted that is a member, for example, corresponding to Y movable section 74 (see Fig. 2) that the substrate stage device of the first embodiment described above has. A pair of X movable sections 774 are synchronously driven in the X-axis direction by an X linear motor by the electromagnetic force drive method that is composed of X stators (the illustration is omitted) that X guides 773 respectively have and X movers (the illustration is omitted) that X movable sections 774 respectively have. The pair of X movable sections 774 each has a holding member 791 that holds substrate holding frame 760 in a noncontact manner using noncontact thrust bearings (the illustration is omitted) such as air bearings or the like, which is similar to holding member 591 that Y movable section 574 of the substrate stage device (see Fig. 13) related to the sixth embodiment described above has. With the configuration as described above, substrate stage device PST₇ related to the seventh embodiment can move substrate holding frame 760 in the X-axis direction with a long stroke, compared with each of the substrate stage devices related to the first to sixth embodiments described above.

Further, substrate holding frame 760 is finely driven in each of the X-axis, Y-axis and θ_z directions as needed, by the X-VCM and the Y-VCM placed on the +Y side of substrate holding frame 760 and the X-VCM and the Y-VCM placed on the

-Y side of substrate holding frame 760. The configurations of the X-VCM and the Y-VCM are the same as those of the X-VCM and the Y-VCM in the sixth embodiment described above. In this case, on the +Y side of substrate holding frame 760, the X-VCM is located on the -X side of the Y-VCM, and on the -Y side of substrate holding frame 760, the X-VCM is located on the +X side of the Y-VCM. Further, the two X-VCMs are located at diagonal positions and the two Y-VCMs are located at diagonal positions with respect to substrate holding frame 760 (such that the centers of the diagonal lines are located in the vicinity of the center of gravity of substrate P).

Consequently, similar to the sixth embodiment described above, substrate P can be driven at the center of gravity (can be driven by making a drive force act on the vicinity of the position of the center of gravity). Consequently, when substrate holding frame 760 is finely driven in the X-axis direction, the Y-axis direction and the θ_z direction using a pair of the X-VCMs and/or a pair of the Y-VCMs, substrate P can be rotated around the vicinity of the position of the center of gravity of a system, as the center, that is composed of substrate holding frame 760 and substrate P.

Moreover, although each of the X-VCMs and the Y-VCMs has a configuration protruding on the +Z side above the upper surface of substrate holding frame 760 (see Fig. 15), it is possible to make substrate holding frame 760 pass below projection optical system PL to move in the X-axis direction, without substrate holding frame 760 interfering with projection optical system PL, because the X-VCMs and the Y-VCMs are located on the +Y side and -Y side of projection optical

system PL (see Fig. 15).

Further, substrate stage device PST₇ has a fifth air levitation unit row that is composed of six air levitation units 50 disposed at a predetermined distance in the Y-axis direction, in an area on the +X side of fixed-point stage 40, which is located on the +X side of the fourth air levitation unit row. And, the third to sixth air levitation units 50 of the fourth air levitation unit row and the second to fourth air levitation units 50 of the fifth air levitation unit row each have main section 51 (see Fig. 15) that is movable in the Z-axis direction (vertically movable), as shown in Fig. 15. In the description below, air levitation units 50 each having main section 51 that is vertically movable as described above are referred to air levitation units 750 for the sake of convenience, in order to distinguish them from the other air levitation units 50 each having main section 51 that is fixed. A leg section 752 of each of a plurality (e.g. eight in this embodiment) of air levitation units 750 is, as shown in Fig. 15, includes a cylinder-like case 752a fixed on surface plate 12 and a shaft 752b one end of which is housed inside case 752a and the other end of which is fixed to support section 52, and which is driven in the Z-axis direction with respect to case 752a, by for example, a uniaxial actuator that is not illustrated such as an air cylinder device or the like.

Referring back to Fig. 14, in substrate stage device PST₇ related to the seventh embodiment, a substrate exchange position is set on the +Z side of the fourth and fifth air levitation unit rows. After the exposure processing on substrate P is completed, the main controller that is not

illustrated releases the holding by adsorption of substrate P using holding unit 65 of substrate holding frame 760 in a state where air levitation units 750 of the fourth and fifth air levitation unit rows are located below (on the -Z side of) substrate P shown in Fig. 14, and in this state, 5
synchronously controls the eight air levitation units 750 respectively, separates substrate P from substrate holding frame 760 and moves substrate P in the +Z direction (see Fig. 15). At the position shown in Fig. 15, substrate P is carried 10
out of substrate stage device PST₇ by a substrate exchanging device that is not illustrated, and after that, a new substrate that is not illustrated is carried to the position shown in Fig. 15. The new substrate is moved in the -Z direction in a state supported by the eight air levitation units 750 from 15
below in a noncontact manner, and then, is held by adsorption by substrate holding frame 760. Incidentally, when substrate P is carried out and carried in by the substrate exchanging device, or when substrate P is delivered to substrate holding frame 760, substrate P and air levitation units 750 can be 20
in a contact state, instead of being in a noncontact state.

In substrate stage device PST₇ as described above, main sections 51 of a plurality of air levitation units 750 are configured movable in the Z-axis direction, and therefore by making substrate holding frame 760 move along the XY plane 25
to be positioned below the substrate exchange position, substrate P can be separated from substrate holding frame 760 and only substrate P can be moved to the substrate exchange position without difficulty.

- Eighth Embodiment

Next, an eighth embodiment is described with reference to Fig. 16. Since a liquid crystal exposure apparatus of the eighth embodiment has a configuration similar to the configuration of each of the liquid crystal exposure apparatuses of the first to seventh embodiments except that a configuration of a substrate stage device is different, only the configuration of the substrate stage device is described below. Incidentally, members which have functions similar to those in the first to seventh embodiments described above are denoted by the same reference signs as the reference signs in the first to seventh embodiments described above and the description thereabout is omitted.

As shown in Fig. 16, a substrate holding frame 860 of a substrate stage device PST₈ related to the eighth embodiment has a pair of X frame members 861x each of which is made up of a plate-shaped member with the X-axis direction serving as its longitudinal direction and which are spaced apart at a predetermined distance in the Y-axis direction, and the -X side end of each of the pair of X frame members 861x is connected to a Y frame members 861y made up of a plate-shaped member with the Y-axis direction serving as its longitudinal direction. Accordingly, substrate holding frame 860 has a U-like outer shape (contour) that is opened on the -X side in a planar view. Therefore, in a state where the holding by adsorption by a plurality of holding units 65 of substrate holding frame 860 is released, substrate P can pass through an opening section formed at the +X side end of substrate holding frame 860 by moving in the +X direction with respect

to substrate holding frame 860. Incidentally, the configuration of drive unit 770 (XY two-dimensional stage device) that guides substrate holding frame 860 along the XY plane during an exposure operation or the like is the same
5 as that of the seventh embodiment described above.

Further, substrate stage device PST₈ of the eighth embodiment has a fifth air levitation unit row, which is composed of six air levitation units 50 disposed at a predetermined distance in the Y-axis direction, in an area
10 on the +X side of fixed-point stage 40, which is located on the +X side of the fourth air levitation unit row. Further, substrate stage device PST₈ has two rows, which are placed at a predetermined distance in the X-axis direction, of air levitation unit rows each of which is composed of four air
15 levitation units 50 disposed at a predetermined distance in the Y-axis direction, in an area on the +X side of surface plate 12 on floor surface F (see Figs. 1 and 3). The upper surface (gas jetting surface) of each of the eight air levitation units 50 in total that configure the two rows of
20 the air levitation unit rows is placed coplanar (flush) with the upper surfaces of a plurality of air levitation units 50 on surface plate 12.

In substrate stage device PST₈ related to the eighth embodiment, substrate P can be drawn in the +X direction from
25 substrate holding frame 860 and can be carried to, for example, the substrate exchange position, in a state where the holding of substrate P by a plurality of holding units 65 of substrate holding frame 860 is released. As a method of carrying substrate P to the substrate exchange position, for example,

a plurality of air levitation units can be provided with an air conveyer function to carry (send) substrate P in a horizontal direction, or a mechanical carrier device can be used. According to substrate stage device PST₈ related to the eighth embodiment, since substrate P can easily and promptly be carried to the substrate exchange position by horizontally moving substrate P, the throughput is improved. Incidentally, a configuration can be employed in which when the substrate is drawn from the substrate holding frame via the opening section, and when the substrate is inserted into the substrate holding frame via the opening section, the holding units that hold the substrate by adsorption can be withdrawn from the movement course of the substrate (e.g. a configuration in which the holding units can be moved in vertical directions or can be housed inside the respective frame members that configure the substrate holding frame). In this case, the exchange of substrates can be performed more reliably.

Incidentally, the first to eighth embodiments described above can appropriately be combined. For example, a substrate holding frame that has a configuration similar to the substrate holding frame of the second embodiment described earlier can be used in each of the substrate stage devices related to the third to sixth embodiments described earlier.

25 - Ninth Embodiment

Next, a ninth embodiment is described. The substrate stage device related to each of the first to eighth embodiments is arranged in a liquid crystal exposure apparatus, whereas a substrate stage device PST₉ related to the present ninth

embodiment is arranged in a substrate inspecting apparatus 900 as shown in Fig. 17.

Substrate inspecting apparatus 900 has a photographic unit 910 that is supported by body BD. Photographic unit 910 has a photographic optical system that includes, for example, an image sensor such as a CCD (Charge-Coupled Device), a lens and the like which are not illustrated, and photographs the surface of substrate P placed directly under (on the -Z side of) photographic unit 910. The outputs from photographic unit 910 (image data of the substrate P surface) are output to the outside, and inspection (e.g. detection of defects of patterns, or particles and the like) of substrate P is performed based on the image data. Note that substrate stage device PST₉, which substrate inspecting apparatus 900 has, has a configuration that is the same as the configuration of substrate stage device PST₁ of the first embodiment described above (see Fig. 1). When the inspection of substrate P is performed, the main controller adjusts the surface position of a portion subject to inspection (a portion directly under photographic unit 910) of substrate P using fixed-point stage 40 (see Fig. 2) such that the surface position is located within a depth of focus of the photographic optical system that photographic unit 910 has. Consequently, clear image data of substrate P can be obtained. Further, since the positioning of substrate P can be performed at high speed and with high precision, the inspection efficiency of substrate P is improved. Incidentally, as the substrate stage device of the substrate inspecting apparatus, either one of the other substrate stage devices related to the second to eighth

embodiments described above can be applied. Incidentally, in the ninth embodiment described above, while the case where inspecting apparatus 900 is based on the imaging method is shown as an example, the inspecting apparatus is not limited to being based on the imaging method but can be based on another method, diffraction/scattering detection, or scatterometry or the like.

Incidentally, in each of the embodiments above, while the position of the substrate within the XY plane is controlled at high speed and with high precision using the substrate holding frame, the substrate holding frame does not necessarily have to be used in the case where each of the embodiments above is applied to an object processing apparatus in which the position of a substrate needs not to be controlled with high precision, and for example, it is also possible to make a plurality of air levitation units have a horizontal carriage function for a substrate using air.

Further, in each of the embodiments above, while the substrate is guided along the horizontal plane by the drive unit (XY two-dimensional stage device) that drives the substrate in the orthogonal two axial directions which are the X-axis and the Y-axis directions, the drive unit should guide the substrate only in one axial direction as far as, for example, the exposure area on the substrate and the substrate are the same in width.

Further, in each of the embodiments above, the plurality of air levitation units support the substrate by levitation so as to make the substrate parallel to the XY plane, but depending on a type of an object that is subject to support,

the configuration of the device that levitates the object is not limited thereto, and for example, the object can be levitated by magnetism or static electricity. Similarly, as the air chuck unit of the fixed-point stage, depending on a type of an object that is subject to holding, a configuration of holding an object that is subject to holding by magnetism or static electricity can also be employed.

Further, in each of the embodiments above, while the positional information of the substrate holding frame within the XY plane is obtained by the laser interferometer system that includes the laser interferometers that irradiate the movable mirrors arranged at the substrate holding frame with the measurement beams, the position measuring device of the substrate holding frame is not limited thereto, and for example, a two-dimensional encoder system can be used. In this case, for example, scales are arranged on the substrate holding frame and the positional information of the substrate holding frame can be obtained by heads fixed to the body or the like, or heads are arranged on the substrate holding frame and the positional information of the substrate holding frame can be obtained using scales fixed, for example, to the body or the like.

Incidentally, in each of the embodiments above, the fixed-point stage can employ a configuration that displaces the area subject to exposure (or the area subject to photographing) of the substrate only in the Z-axis direction, of the Z-axis direction and the θ_x and θ_y directions.

Further, in each of the embodiments above, while the substrate holding frame has an outer shape (contour) that is

rectangular in a planar view and the opening section that is rectangular in a planar view, the shape of the member that holds the substrate is not limited thereto, and for example, the shape can appropriately be changed in accordance with the shape of an object that is subject to holding (e.g. when an object is discoidal, a holding member can also have a circular frame shape).

Incidentally, in each of the embodiments above, the substrate holding frame does not have to enclose the whole periphery of the substrate, and it is also possible that a part of the periphery is not enclosed. Further, a member to hold the substrate such as the substrate holding frame does not necessarily have to be used for substrate carriage. In this case, it is necessary to measure the position of the substrate itself, and the position of the substrate can be measured by, for example, an interferometer that irradiates a measurement beam on the side surface of the substrate that serves as a mirror surface. Or, it is also possible that a grating is formed on the front surface (or the rear surface) of the substrate and the position of the substrate is measured by an encoder equipped with a head that irradiates the grating with a measurement light and receives diffraction light of the measurement light.

Further, the illumination light can be ultraviolet light, such as ArF excimer laser light (with a wavelength of 193 nm) and KrF excimer laser light (with a wavelength of 248 nm), or vacuum ultraviolet light such as F₂ laser light (with a wavelength of 157 nm). Further, as the illumination light, a harmonic wave, which is obtained by amplifying a

single-wavelength laser light in the infrared or visible range emitted by a DFB semiconductor laser or fiber laser with a fiber amplifier doped with, for example, erbium (or both erbium and ytterbium), and by converting the wavelength into
5 ultraviolet light using a nonlinear optical crystal, can also be used. Further, solid state laser (with a wavelength of 355 nm, 266 nm) or the like can also be used.

Further, in each of the embodiments above, while the case has been described where projection optical system PL is the
10 projection optical system by a multi-lens method that is equipped with a plurality of optical systems, the number of the projection optical systems is not limited thereto, but there should be one or more projection optical systems.

Further, the projection optical system is not limited to the
15 projection optical system by a multi-lens method, but can be a projection optical system using, for example, a large mirror of the Offner type, or the like. Further, while the case has been described where the projection optical system whose projection magnification is equal magnification is used as
20 projection optical system PL in each of the embodiments above, this is not intended to be limiting, and the projection optical system can be either of a reduction system or a magnifying system.

Further, in each of the embodiments above, while the case
25 has been described where the exposure apparatus is a scanning stepper, this is not intended to be limiting, and each of the embodiments above can also be applied to a static type exposure apparatus such as a stepper. Further, each of the embodiments above can also be applied to a projection exposure apparatus

by a step-and-stitch method that synthesizes a shot area and a shot area. Further, each of the embodiments above can also be applied to an exposure apparatus by a proximity method that does not use any projection optical systems.

5 Further, the application of the exposure apparatus is not limited to the exposure apparatus for liquid crystal display elements in which a liquid crystal display element pattern is transferred onto a rectangular glass plate, but each of the embodiments above can also be widely applied, for
10 example, to an exposure apparatus for manufacturing semiconductors, and an exposure apparatus for producing thin-film magnetic heads, micromachines, DNA chips, and the like. Further, each of the embodiments above can be applied not only to an exposure apparatus for producing microdevices
15 such as semiconductor devices, but can also be applied to an exposure apparatus in which a circuit pattern is transferred onto a glass substrate, a silicon wafer or the like to produce a mask or a reticle used in a light exposure apparatus, an EUV exposure apparatus, an X-ray exposure apparatus, an
20 electron-beam exposure apparatus, and the like. Incidentally, an object that is subject to exposure is not limited to a glass plate, but for example, can be another object such as a wafer, a ceramic substrate, a film member, or a mask blank.

Incidentally, the object processing apparatus related
25 to each of the embodiments above can be applied not only to the exposure apparatus but also to, for example, an element manufacturing apparatus equipped with a functional liquid deposition device by an ink-jet method.

Incidentally, the disclosures of all publications, the

PCT International Publications, the U.S. Patent Application Publications and the U.S. Patents that are cited in the description so far and are related to exposure apparatuses and the like are each incorporated herein by reference.

5

- Device manufacturing method

A manufacturing method of a microdevice that uses the exposure apparatus in each of the embodiments above in a lithography process is described next. In the exposure apparatus in each of the embodiments above, a liquid crystal display element as a microdevice can be obtained by forming a predetermined pattern (such as a circuit pattern or an electrode pattern) on a plate (a glass substrate).

10

- Pattern forming process

First of all, a so-called optical lithography process in which a pattern image is formed on a photosensitive substrate (such as a glass substrate coated with a resist) is executed using the exposure apparatus in each of the embodiments above. In this optical lithography process, a predetermined pattern that includes many electrodes and the like is formed on the photosensitive substrate. After that, the exposed substrate undergoes the respective processes such as a development process, an etching process and a resist removing process, and thereby the predetermined pattern is formed on the substrate.

20

25

- Color filter forming process

Next, a color filter in which many sets of three dots corresponding to R (Red), G (Green) and B (blue) are disposed in a matrix shape, or a color filter in which a plurality of

sets of filters of three stripes of R, G and B are disposed in horizontal scanning line directions is formed.

- Cell assembling process

Next, a liquid crystal panel (a liquid crystal cell) is assembled using the substrate having the predetermined pattern obtained in the pattern forming process, the color filter obtained in the color filter forming process, and the like. For example, a liquid crystal panel (a liquid crystal cell) is manufactured by injecting liquid crystal between the substrate having the predetermined pattern obtained in the pattern forming process and the color filter obtained in the color filter forming process.

- Module assembling process

After that, a liquid crystal display element is completed by attaching respective components such as an electric circuit that causes a display operation of the assembled liquid crystal panel (liquid crystal cell) to be performed, and a backlight.

In this case, since exposure of the plate is performed with high throughput and high precision using the exposure apparatus in each of the embodiments above in the pattern forming process, the productivity of liquid crystal display elements can be improved as a consequence.

Industrial Applicability

As described above, the object processing apparatus of the present invention is suitable for performing predetermined processing with respect to a tabular object. Further, the exposure apparatus and the exposure method of

the present invention are suitable for exposing a tabular object with an energy beam. Further, the device manufacturing method of the present invention is suitable for production of microdevices.

Claims

1. An object processing apparatus that performs predetermined processing to a tabular object placed along a
5 predetermined two-dimensional plane that includes a first axis and a second axis orthogonal to each other, the apparatus comprising:

an executing device that executes a predetermined operation on a partial area on one surface side of the object;

10 an adjustment device which has a holding surface that holds a section, including the partial area, of the object in a noncontact state from below the object, and which adjusts a position of the section in a direction intersecting the two-dimensional plane; and

15 a noncontact support device that supports the object in a noncontact manner from below, with its support surface made to be opposed to the other area, excluding the section held by the adjustment device, of the object.

20 2. The object processing apparatus according to claim 1, wherein

the adjustment device holds the object in a noncontact manner by jetting a gas from the holding surface to the object and suctioning a gas between the holding surface and the
25 object.

3. The object processing apparatus according to claim 2, wherein

the adjustment device causes at least one of a pressure

and a flow rate of the gas between the object and holding surface to be variable such that a distance between the object and the holding surface is constant.

5 4. The object processing apparatus according to any one of claims 1 to 3, wherein

the adjustment device has an actuator that drives a member having the holding surface in the direction intersecting the two-dimensional plane.

10

5. The object processing apparatus according to claim 4, wherein

15 the actuator includes a mover arranged at the member having the holding surface and a stator arranged at a member that is separated, in terms of vibration, from a measurement member that measures positional information of the member having the holding surface.

20 6. The object processing apparatus according to any one of claims 1 to 5, wherein

the adjustment device has a weight cancelling device that cancels a weight of the object.

25 7. The object processing apparatus according to any one of claims 1 to 6, wherein

the noncontact support device supports the object in a noncontact manner by jetting a gas from the support surface to the object.

8. The object processing apparatus according to any one of claims 1 to 7, wherein

the distance between the holding surface of the adjustment device and the object is shorter than a distance
5 between the support surface of the noncontact support device and the object.

9. The object processing apparatus according to any one of claims 1 to 8, further comprising:

10 a movable body that holds an end of the object and is movable along the two-dimensional plane; and

a drive device that drives the movable body at least in one axial direction within the two-dimensional plane.

15 10. The object processing apparatus according to claim 9, wherein

the member having the holding surface of the adjustment device is separated from the drive device in terms of vibration.

20

11. The object processing apparatus according to one of claims 9 and 10, wherein

the support surface of the noncontact support device covers a movement range of the object where the object moves
25 when being driven by the drive device.

12. The object processing apparatus according to any one of claims 9 to 11, wherein

at least a part of the support surface of the noncontact

support device is arranged to be movable in the direction intersecting the two-dimensional plane, and the noncontact support device separates the object from the movable body and moves the object in the direction intersecting the
5 two-dimensional plane, by movement of the at least a part of the support surface in the direction intersecting the two-dimensional plane.

13. The object processing apparatus according to any
10 one of claims 9 to 12, wherein

the movable body has a main section that is made up of a frame-shaped member arranged extending along the end of the object.

15 14. The object processing apparatus according to claim 13, wherein

the movable body has a holding member that holds by adsorption at least a part of an outer periphery of the object from below, and

20 the holding member can be displaced in a direction orthogonal to the two-dimensional plane in a state holding the object, with respect to the main section.

15 25 15. The object processing apparatus according to claim 14, wherein

the holding member is arranged protruding below a lower surface of the object, and a distance of the protrusion is less than a distance between the support surface of the noncontact support device and the lower surface of the object.

16. The object processing apparatus according to any one of claims 13 to 15, wherein

the main section has an opening section that allows
5 passing of the object by relative movement of the main section with respect to the object in a direction parallel to the two-dimensional plane.

17. The object processing apparatus according to claim
10 13, wherein

the movable body has a pressing device that causes the main section to hold the object by pressing the object from one of a pair of opposed surfaces that is opposed to each other, toward the other of the opposed surfaces, the opposed surfaces
15 being of inner wall surfaces of the main section.

18. The object processing apparatus according to any one of claims 13 to 17, further comprising:

an optical interferometer system that obtains
20 positional information of the main section within the two-dimensional plane, by irradiating each of a first outer side surface and a second outer side surface of the main section with a measurement beam and receiving reflected light of the measurement beam, the first outer side surface being
25 orthogonal to the first axis and the second outer side surface being orthogonal to the second axis.

19. The object processing apparatus according to any one of claims 13 to 18, wherein

the drive device includes a first guide member arranged extending parallel to the first axis, a first movable member that moves in a direction parallel to the first axis on the first guide member, a second guide member arranged extending parallel to the second axis and connected to the first movable member, and a second movable member that holds the movable body and moves in a direction parallel to the second axis on the second guide member, and

the first guide member and the first movable member are placed lower than the predetermined two-dimensional plane.

20. The object processing apparatus according to claim 19, wherein

a plurality of the first guide members are arranged at a predetermined distance in the direction parallel to the second axis,

a plurality of the first movable members are arranged so as to correspond to the plurality of the first guide members, and

the second guide member is installed over the plurality of the first movable members.

21. The object processing apparatus according to one of claims 19 and 20, wherein

the second guide member is placed higher than the support surface of the noncontact support device and a lower surface of the second guide member is supported in a noncontact state by the noncontact support device.

22. The object processing apparatus according to any one of claims 19 to 21, wherein

the second movable member is supported in a noncontact manner by the second guide member.

5

23. The object processing apparatus according to any one of claims 19 to 22, wherein

a plurality of the second movable members are placed at a predetermined distance in the direction parallel to the

10 second axis, and

a plurality of portions of the movable body are held by the plurality of the second movable members.

24. The object processing apparatus according to any one of claims 19 to 23, wherein

the movable body is held in a noncontact manner by the second movable member.

25. The object processing apparatus according to claim 20 24, wherein

the drive device comprises a fine drive device that finely drives the movable body with respect to the second movable member in the direction parallel to the two dimensional plane.

25

26. The object processing apparatus according to any one of claims 19 to 25, wherein

the first movable member is arranged on each of one side and the other side of the movable body in one axial direction

within the two-dimensional plane,

the second guide member and the second movable member are arranged so as to correspond to the first movable member on the one side and the first movable member on the other side, respectively, and

the one side and the other side of the movable body in the one axial direction are held by the second movable member on the one side and the second movable member on the other side, respectively.

10

27. The object processing apparatus according to any one of claims 19 to 26, wherein

the movable body is connected to the second movable member via a hinge device that allows rotation of the movable body and the second movable member around an axis line parallel to the two-dimensional plane while restricting relative movement between the movable body and the second movable member in the direction parallel to the two-dimensional plane.

20

28. The object processing apparatus according to any one of claims 9 to 27, further comprising:

an optical interferometer system that obtains positional information of the movable body within the two-dimensional plane, by irradiating a reflection surface arranged at the movable body with a measurement beam and receiving reflected light of the measurement beam.

25

29. The object processing apparatus according to any one of claims 1 to 28, wherein

the executing device includes an imaging device that picks up an image of a surface of the object to inspect the object.

5 30. The object processing apparatus according to any one of claims 1 to 29, wherein

the object is a substrate used for a display panel of a display device.

10 31. The object processing apparatus according to any one of claims 1 to 28, wherein

the executing device is a pattern forming device that forms a predetermined pattern on the object by exposing the object with an energy beam.

15

32. A device manufacturing method, comprising:
exposing the object using the object processing apparatus according to claim 31; and
developing the exposed object.

20

33. An exposure apparatus that exposes an object by irradiating the object with an energy beam and forms a predetermined pattern on the object, the apparatus comprising:

25

a fixed-point stage which includes a member that holds a section, including a partial area on which the energy beam is irradiated, of the object placed along a predetermined two-dimensional plane that includes a first axis and a second axis orthogonal to each other, in a noncontact state from below

the object, and which adjusts a position of the section in a direction intersecting the two-dimensional plane; and

a noncontact support device that supports the object in a noncontact manner from below, with its support surface made to be opposed to the other area, excluding the section held
5 by the holding surface, of the object.

34. The exposure apparatus according to claim 33, further comprising:

10 an object holding member that holds an end of the object and is movable along the two-dimensional plane; and

a drive device that drives the object holding member at least in one axial direction within the two-dimensional plane.

15 35. The exposure apparatus according to claim 34, further comprising:

an optical interferometer system that obtains positional information of the object holding member within the two-dimensional plane, by irradiating a reflection
20 surface arranged at the object holding member with a measurement beam and receiving reflected light of the measurement beam.

25 36. The exposure apparatus according to any one of claims 33 to 35, wherein

the fixed-point stage has an actuator that drives a member having the holding surface in the direction intersecting the two-dimensional plane.

37. The exposure apparatus according to claim 36,
wherein

the actuator includes a mover arranged at the member
having the holding surface and a stator arranged at a member
5 that is separated, in terms of vibration, from a measurement
member that measures positional information of the member
having the holding surface.

38. The exposure apparatus according to any one of
10 claims 33 to 37, wherein

the fixed-point stage has a weight cancelling device
that cancels a weight of the object.

39. The exposure apparatus according to any one of
15 claims 33 to 38, wherein

the object is a substrate with a size not less than 500
mm.

40. A device manufacturing method, comprising:
20 exposing the object using the exposure apparatus
according to any one of claims 33 to 39; and
developing the exposed object.

41. A flat-panel display manufacturing method,
25 comprising:

exposing a substrate for a flat-panel display using the
exposure apparatus according to any one of claims 33 to 39;
and

developing the substrate that has been exposed.

42. An exposure method of exposing an object by irradiating the object with an energy beam and forming a predetermined pattern on the object, the method comprising:

5 holding a section, including a partial area on which the energy beam is irradiated, of the object placed along a predetermined two-dimensional plane that includes a first axis and a second axis orthogonal to each other, in a noncontact state from below the object by a holding member whose position
10 within the two-dimensional plane is fixed, and adjusting a position of the section in a direction intersecting the two-dimensional plane; and

supporting the object in a noncontact manner from below, with a support surface of a support member made to be opposed
15 to the other area, excluding the section held by the holding member, of the object.

43. The exposure method according to claim 42, further comprising:

20 holding an end of the object by an object holding member that is movable along the two-dimensional plane; and
driving the object holding member at least in one axial direction within the two-dimensional plane.

25 44. A device manufacturing method, comprising:
exposing the object using the exposure method according to one of claims 42 and 43; and
developing the exposed object.

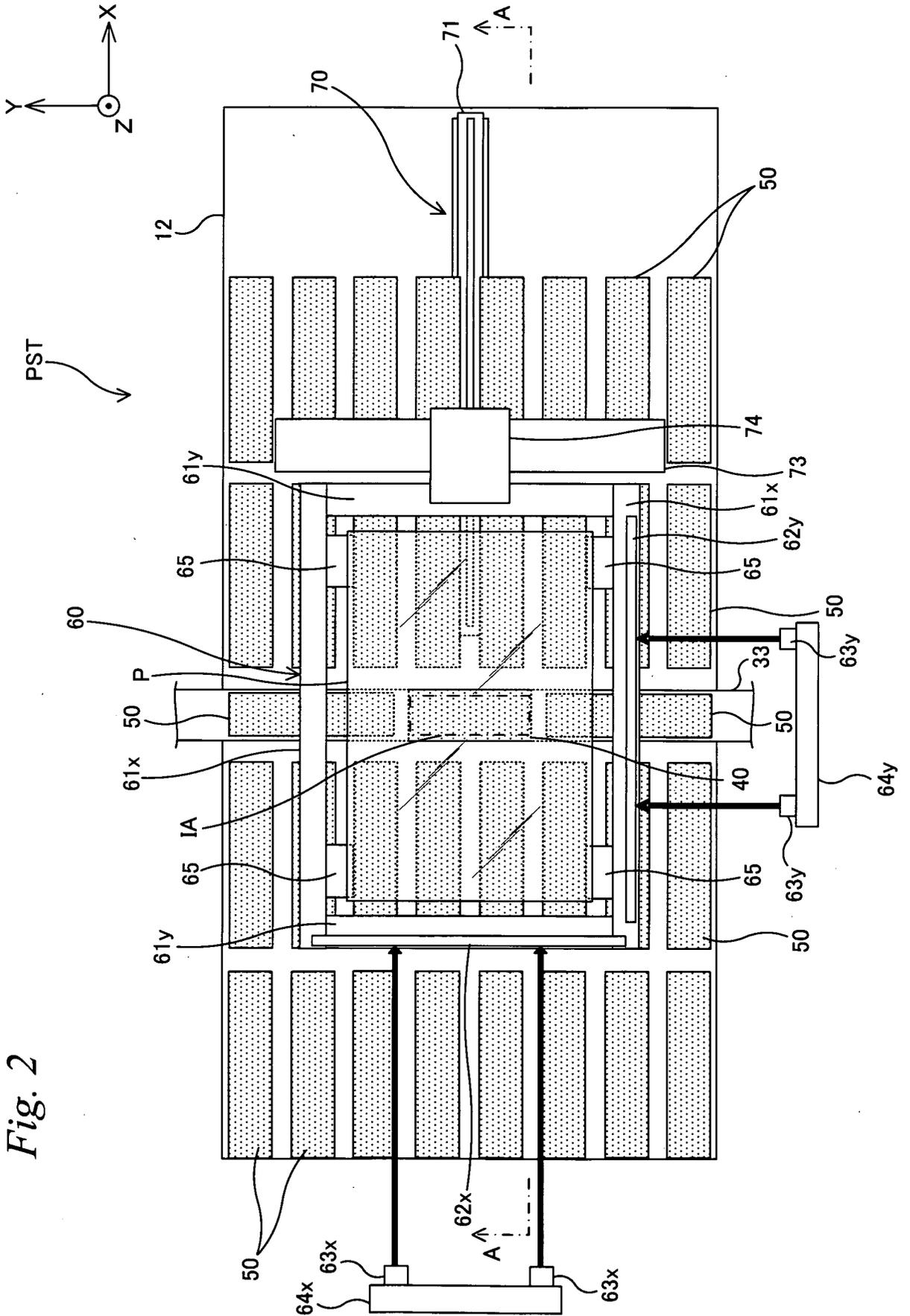


Fig. 3

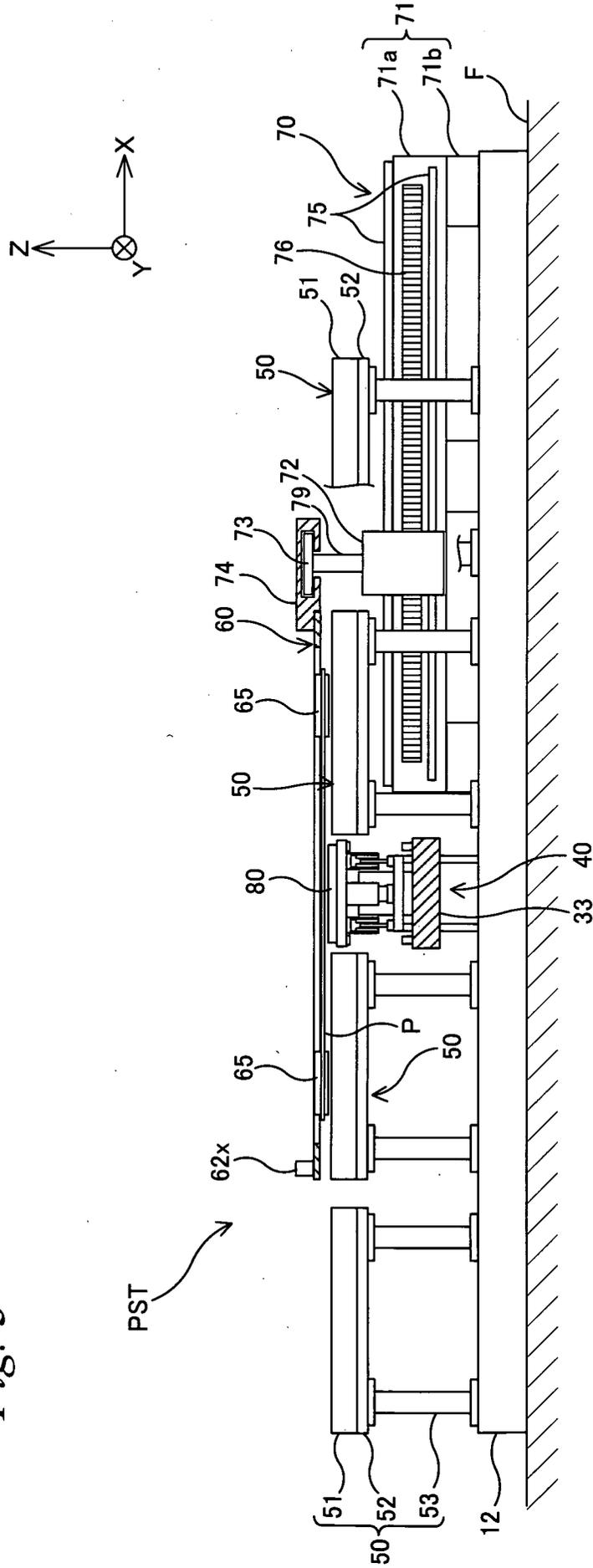
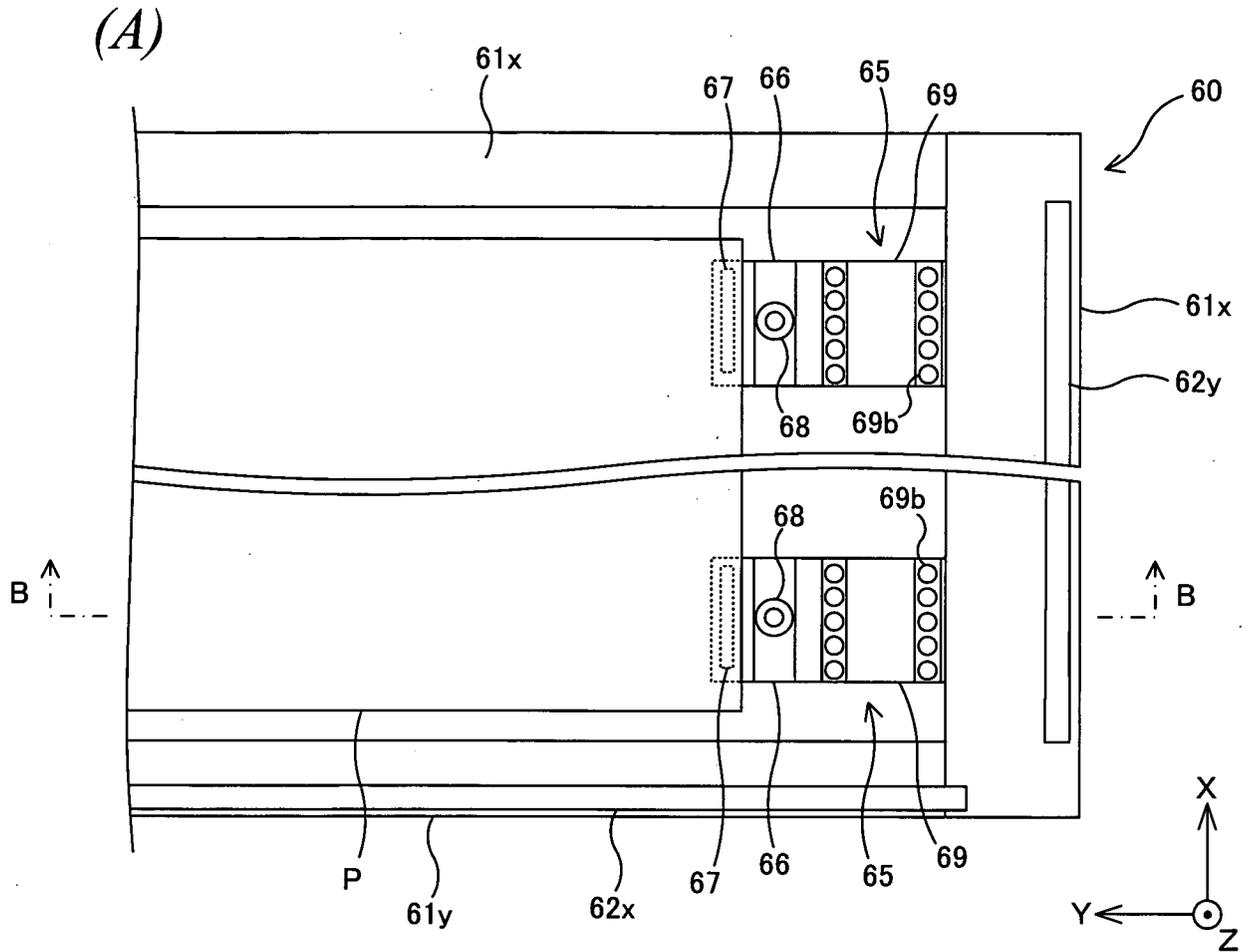


Fig. 5



(B)

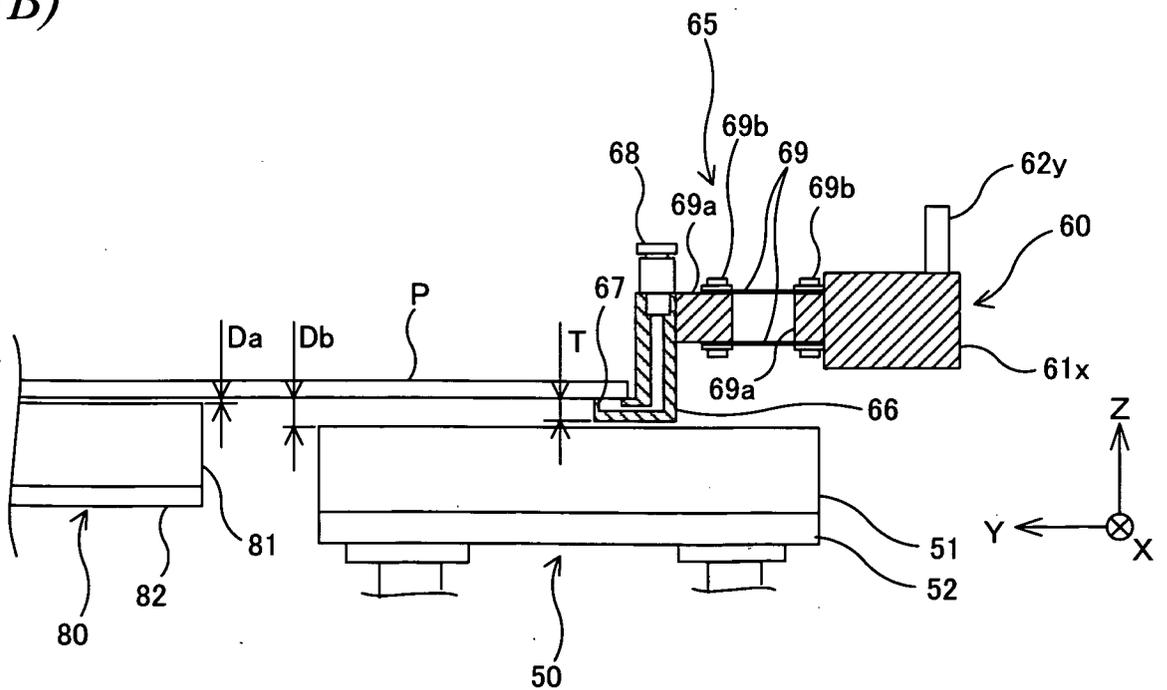


Fig. 6

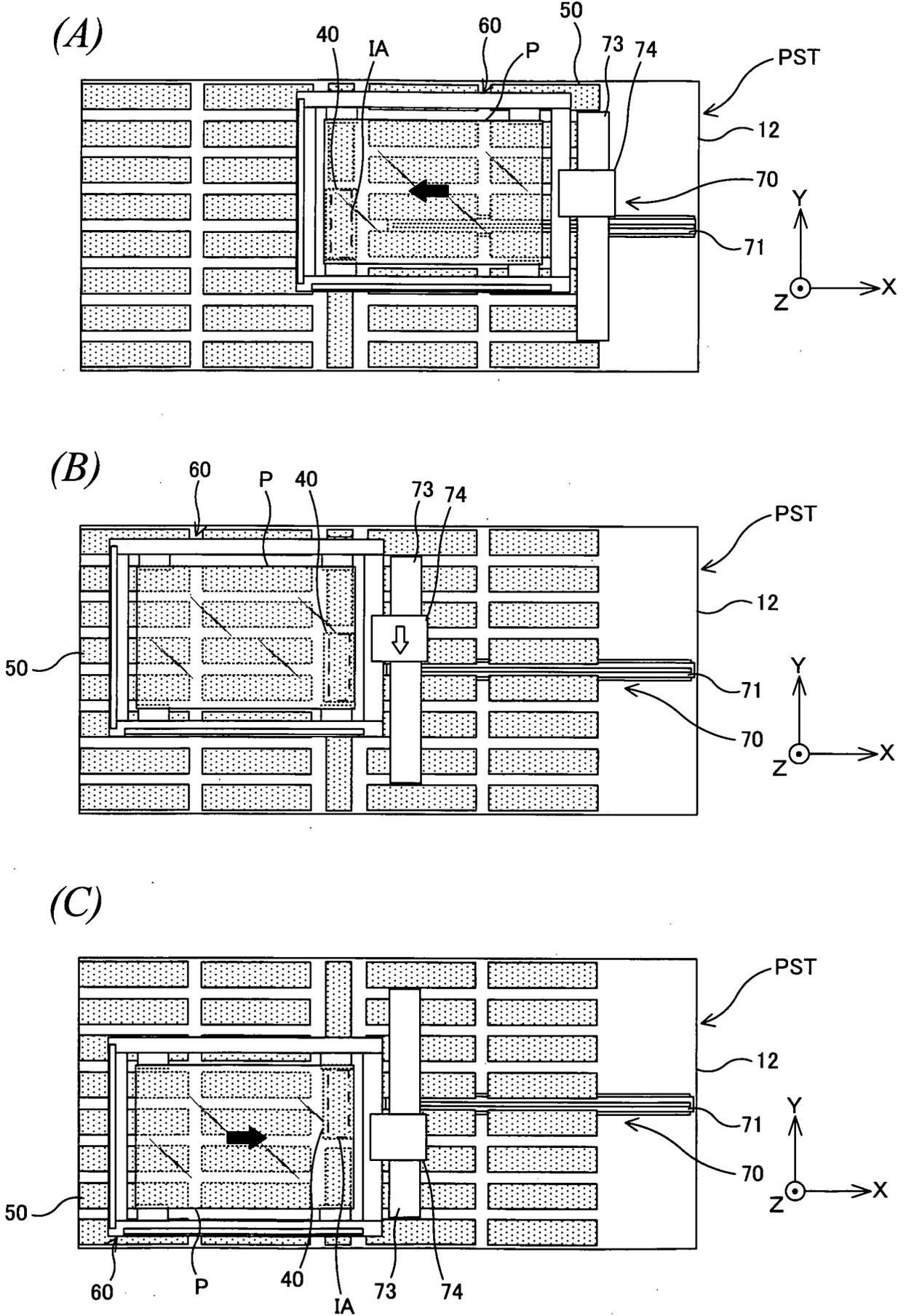
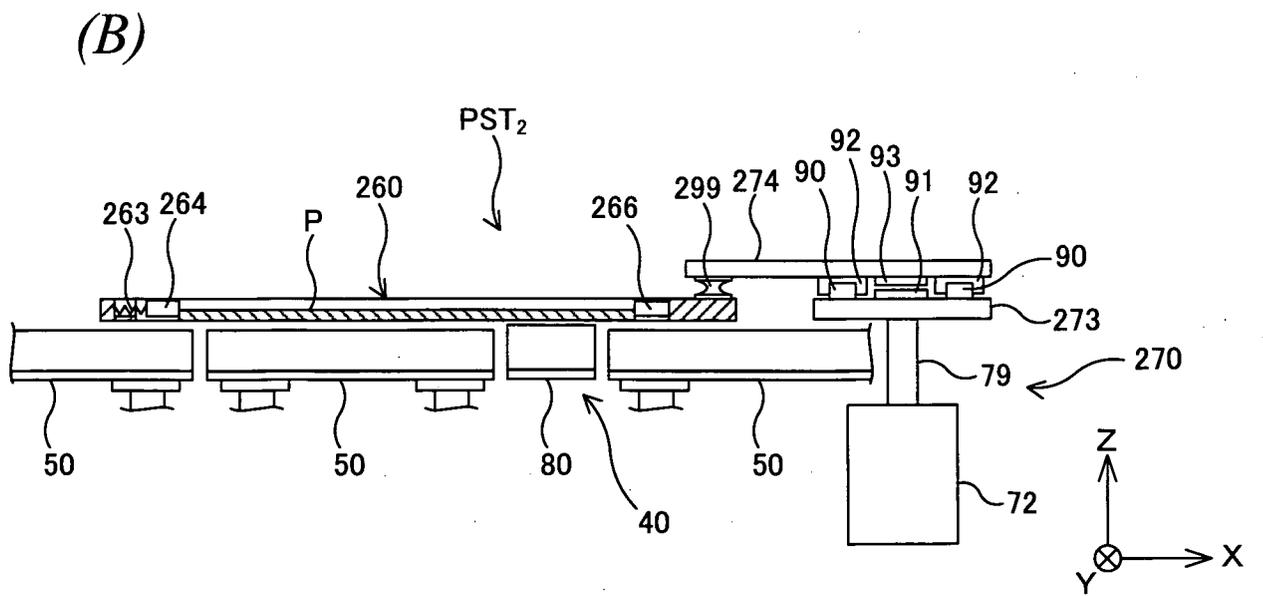
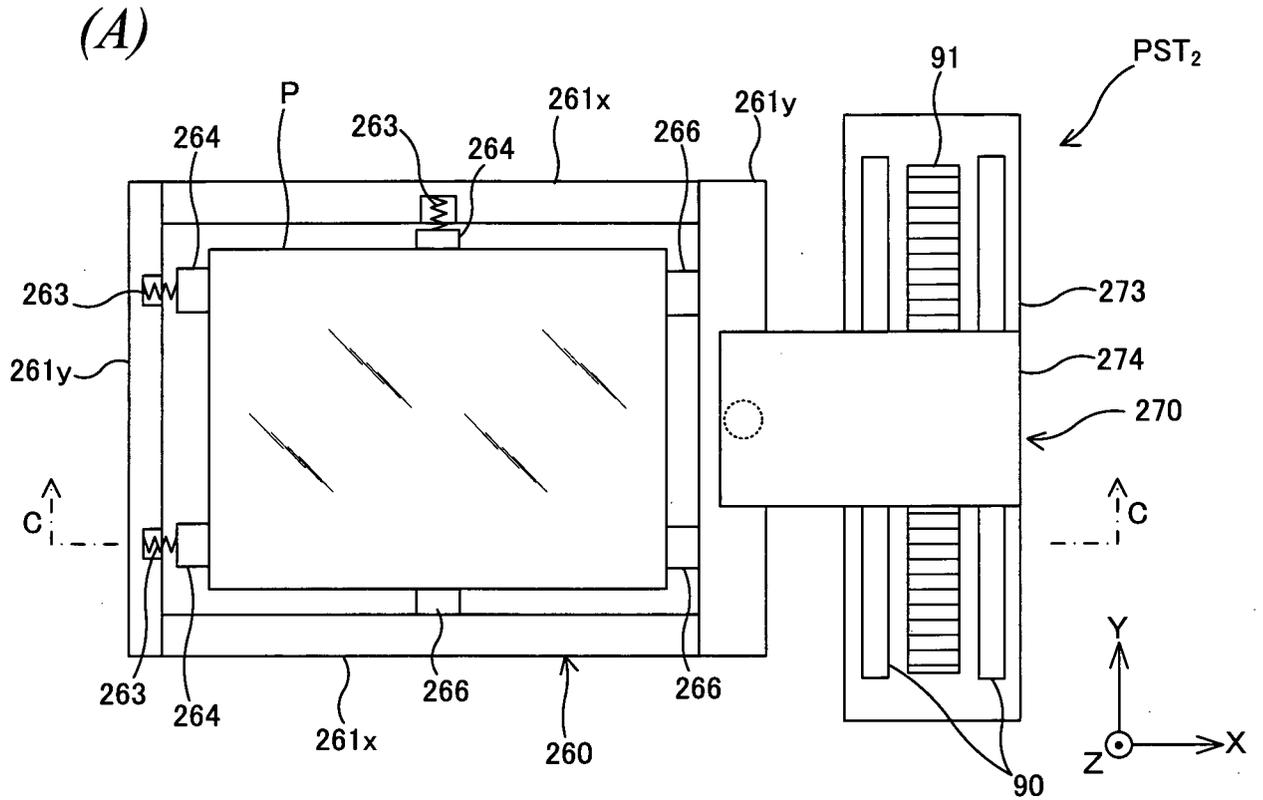


Fig. 7



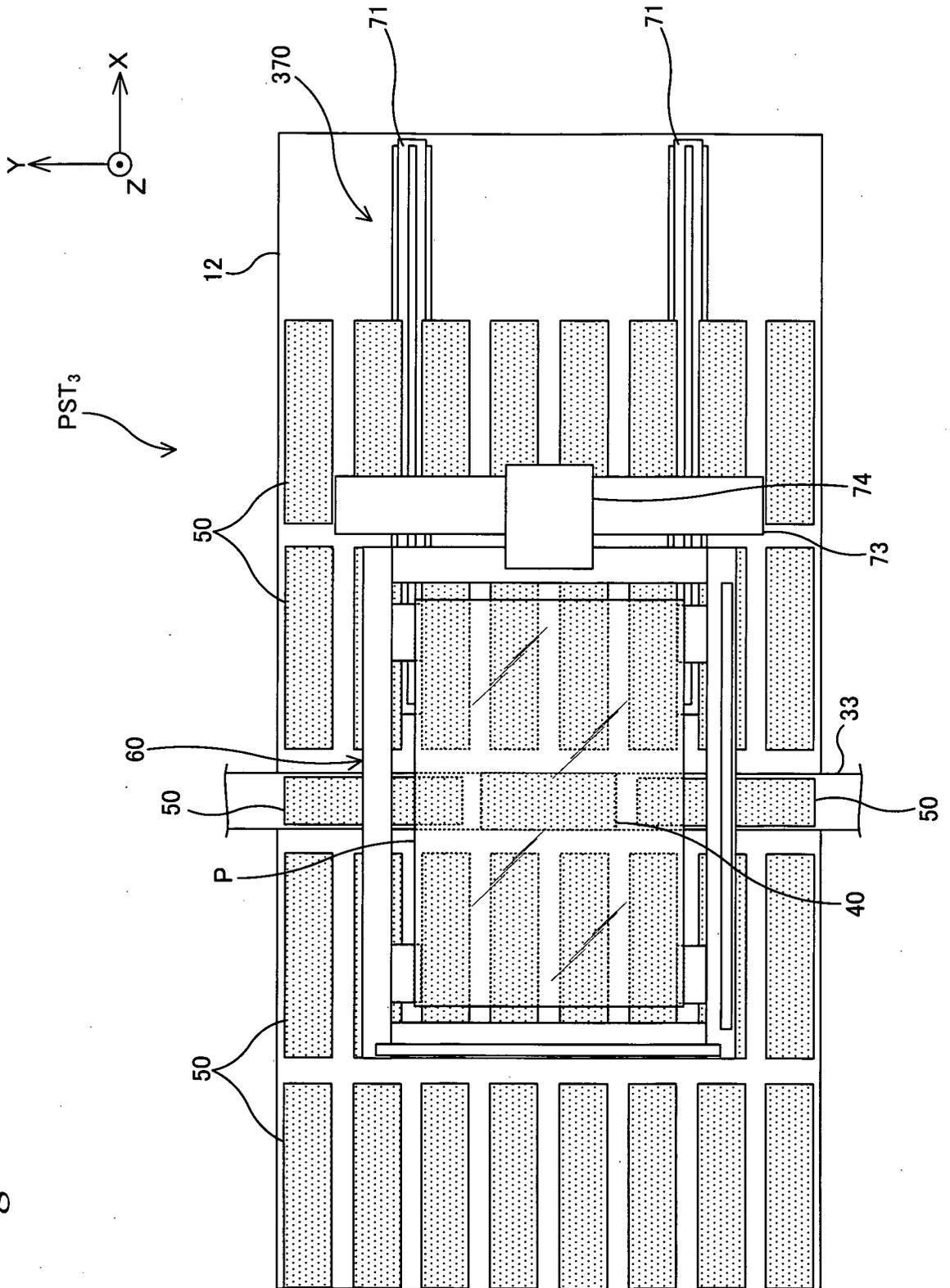


Fig. 8

Fig. 9

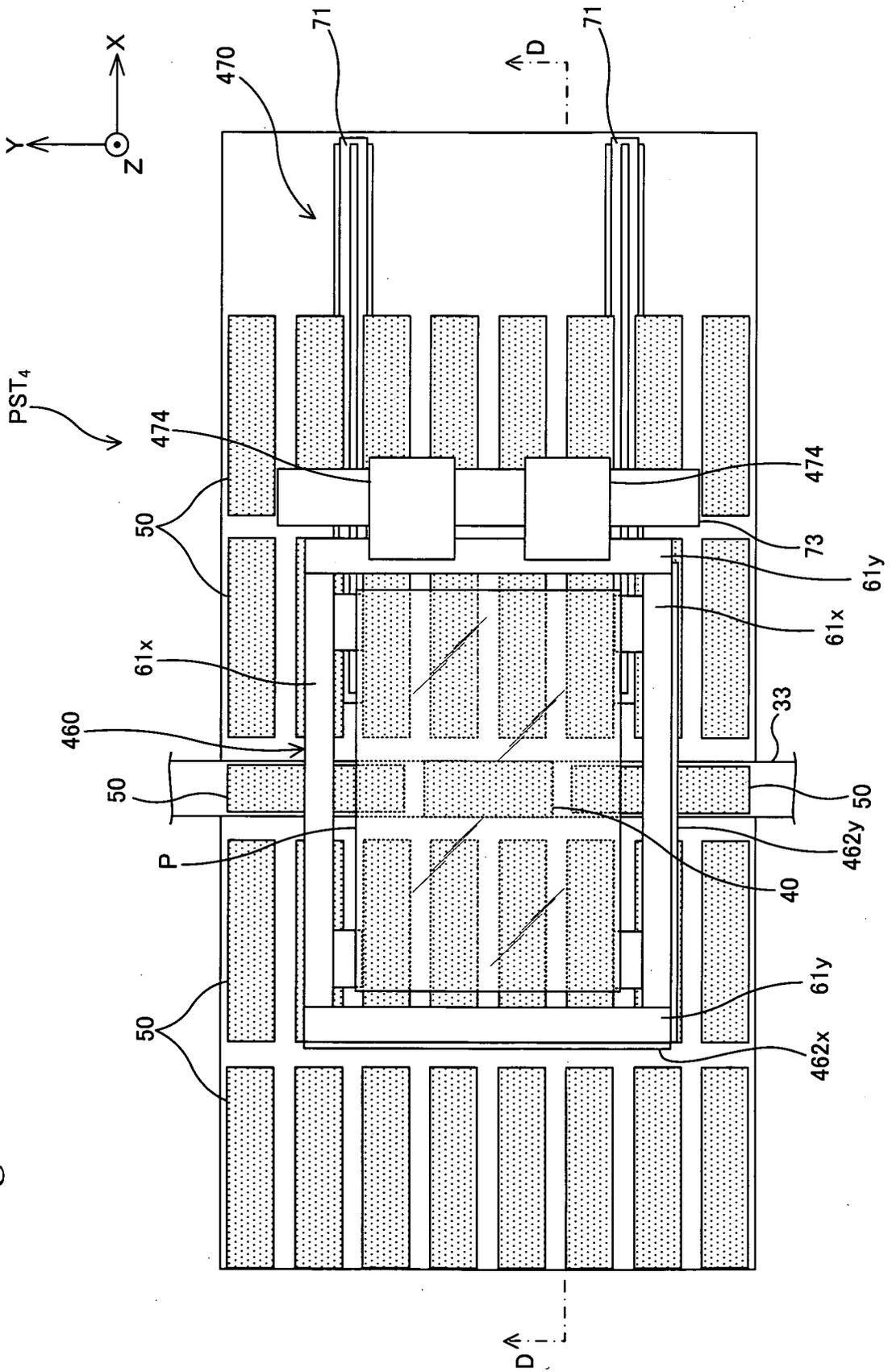
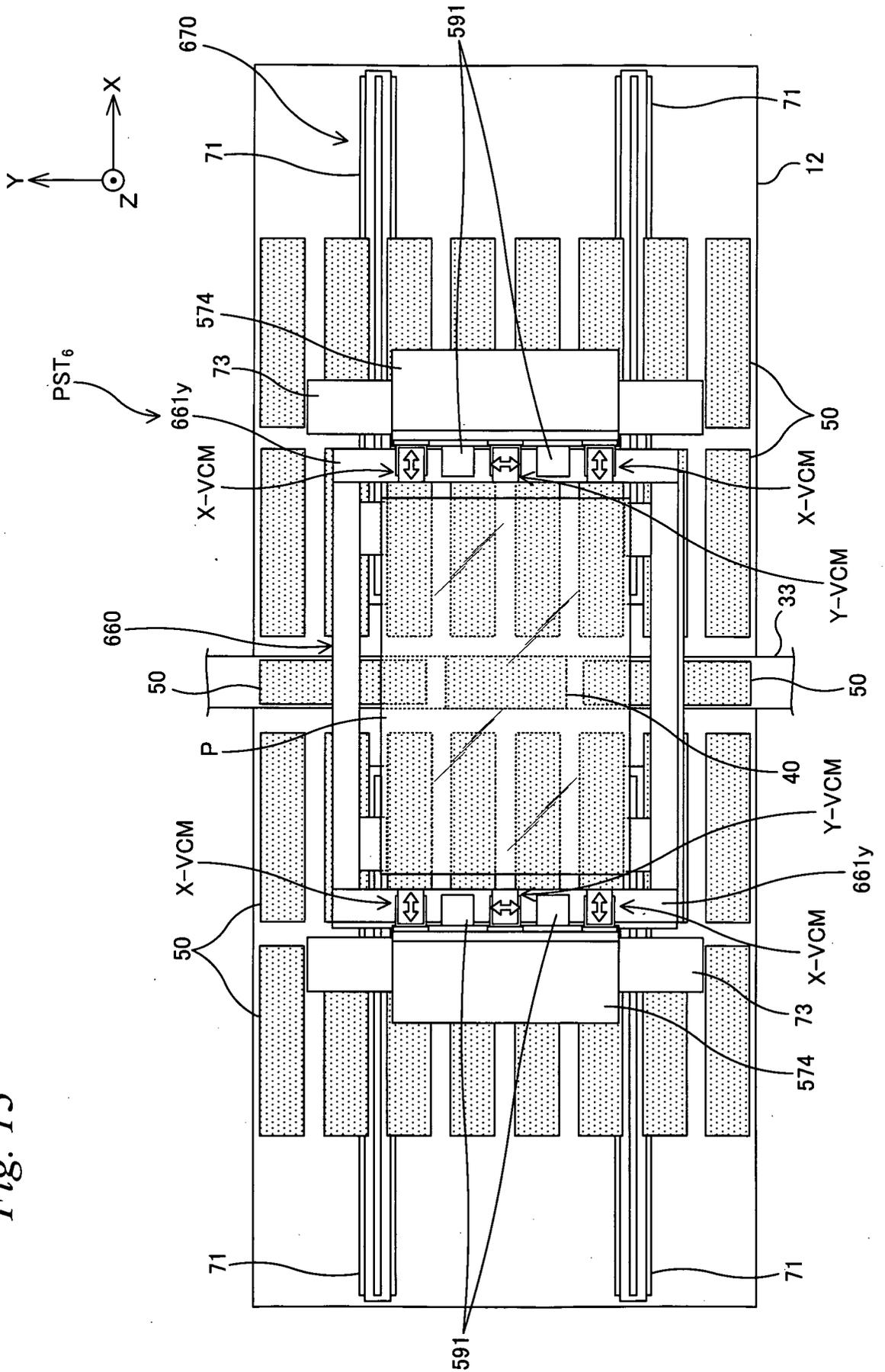


Fig. 13



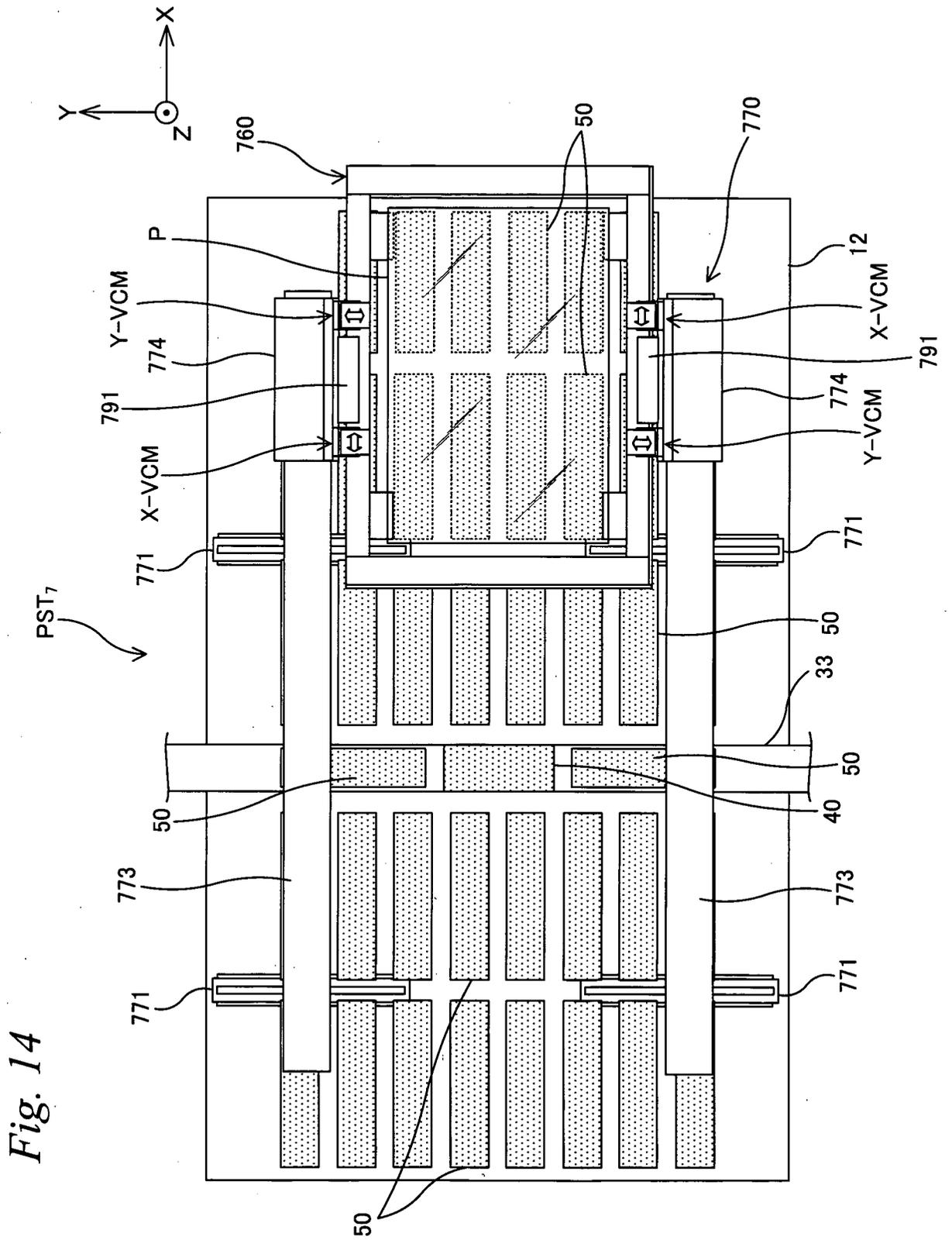


Fig. 15

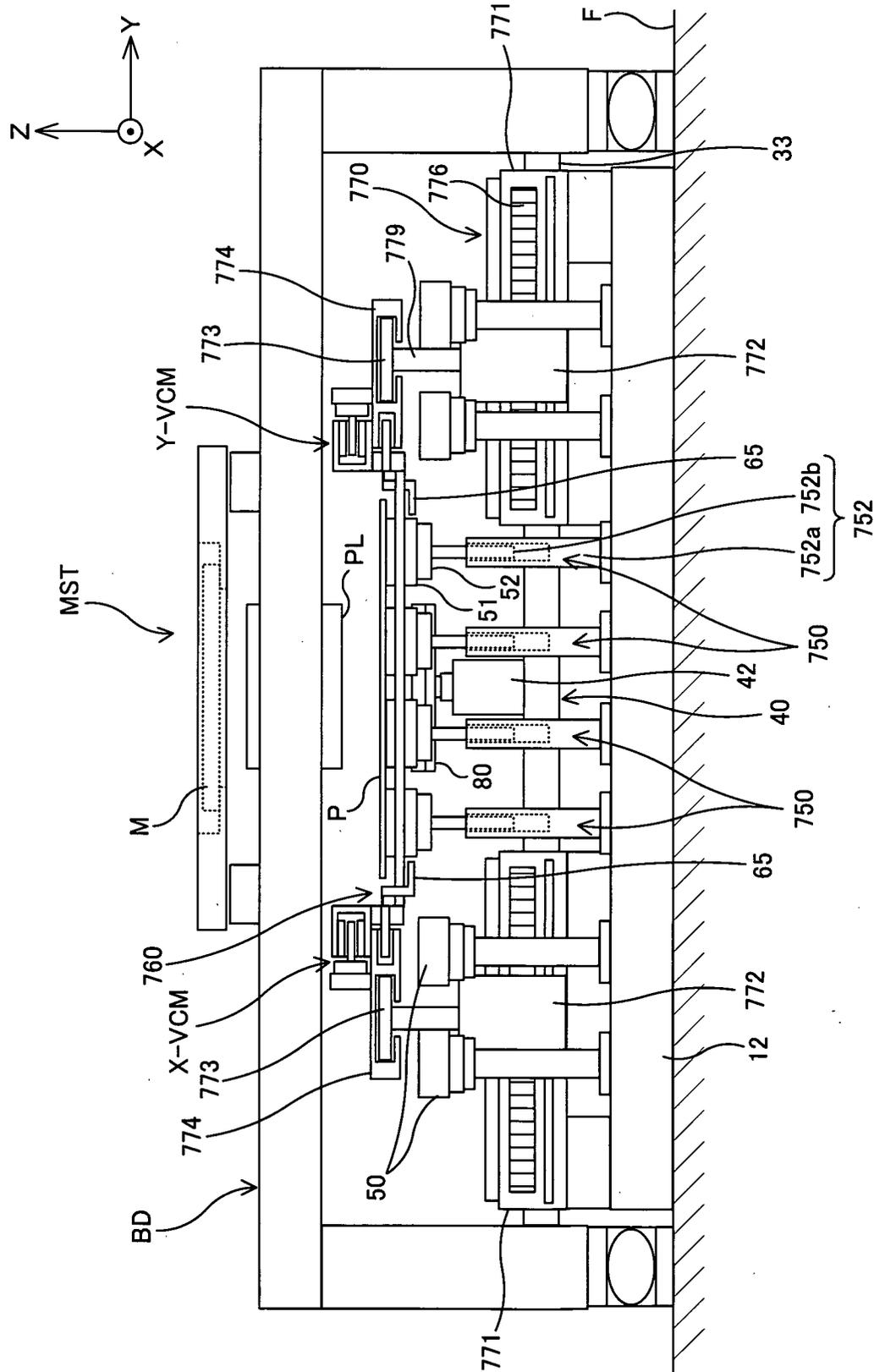


Fig. 16

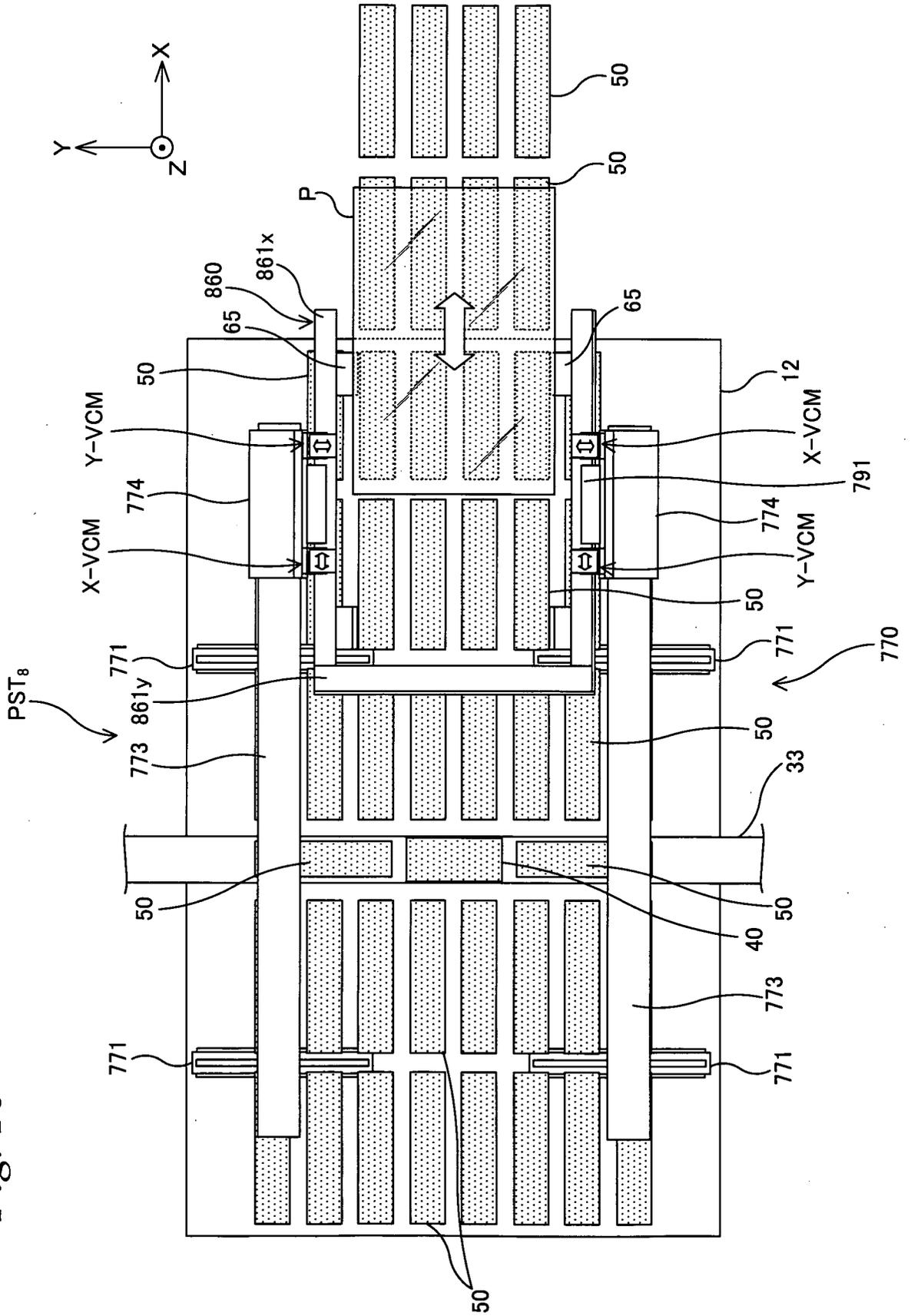
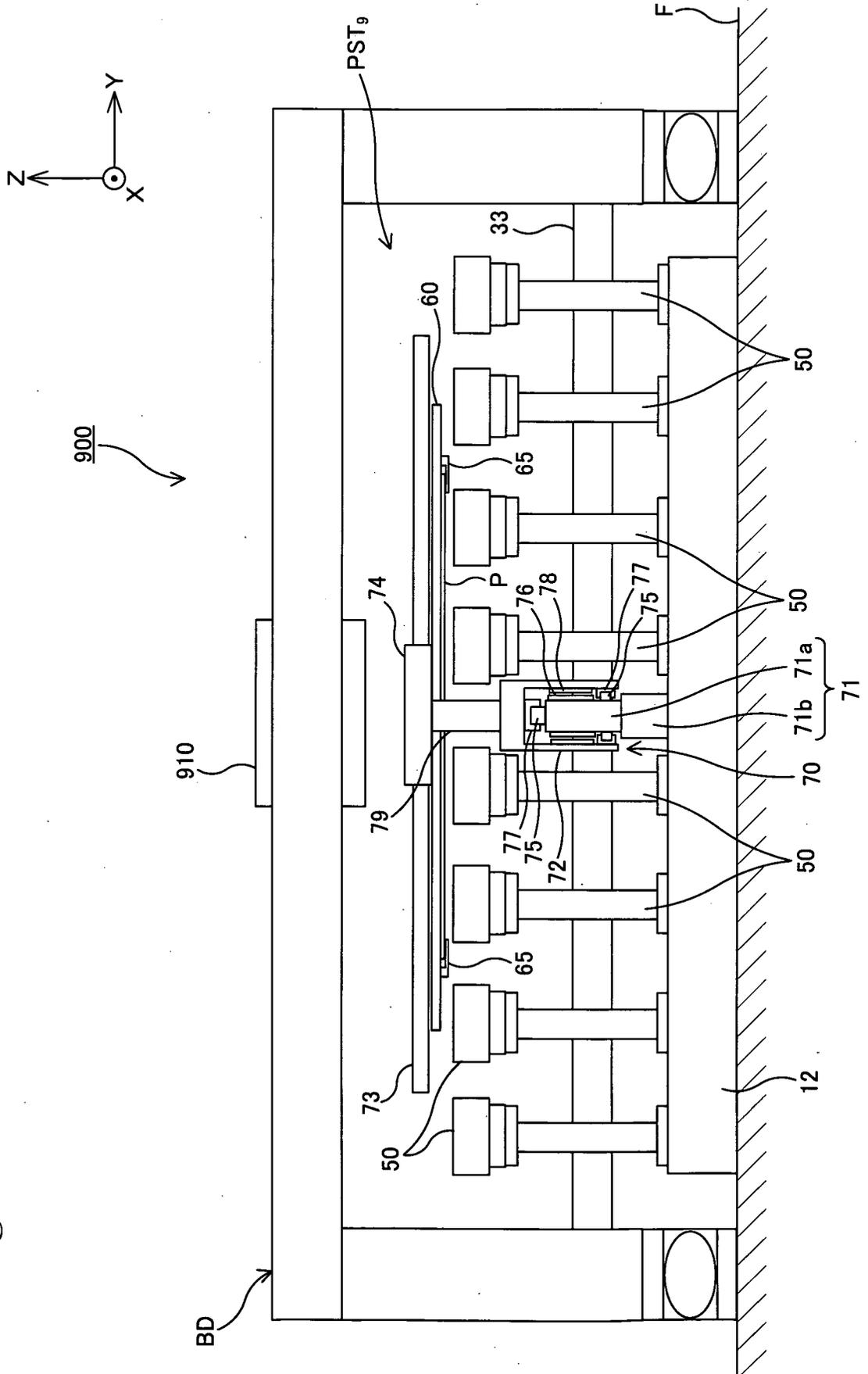


Fig. 17



INTERNATIONAL SEARCH REPORT

International application No
PCT/JP2010/064134

A. CLASSIFICATION OF SUBJECT MATTER INV. G03F7/20 B65G49/06 H01L21/68 ADD.		
According to International Patent Classification (IPC) or to both national classification and IPC		
B. FIELDS SEARCHED Minimum documentation searched (classification system followed by classification symbols) G03F B65G H01L		
Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched		
Electronic data base consulted during the international search (name of data base and, where practical, search terms used) EPO-Internal		
C. DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2007/195653 A1 (YASSOUR YUVAL [IL] ET AL) 23 August 2007 (2007-08-23)	1-3,7, 9-26, 28-35, 39-44
Y	paragraphs [0142] - [0168], [0190] - [0194], [0241]; figures 3-4f,6b,7a-7e,9b-10b	4-6,8, 27,36-38
X	US 2005/040338 A1 (WEISS ADAM [CA] ET AL) 24 February 2005 (2005-02-24)	1-3,7-11
Y A	paragraphs [0050] - [0060]; figure 5A	4-6,8 29,30
X	US 2006/098176 A1 (GUI CHENG-QUN [NL] ET AL GUI CHENG-QUN [NL] ET AL) 11 May 2006 (2006-05-11)	1,33,42
Y	paragraphs [0062] - [0063], [0071] - [0079]; figures 2,3	4-6, 36-38
	-/--	
<input checked="" type="checkbox"/> Further documents are listed in the continuation of Box C. <input checked="" type="checkbox"/> See patent family annex.		
* Special categories of cited documents : "A" document defining the general state of the art which is not considered to be of particular relevance "E" earlier document but published on or after the international filing date "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) "O" document referring to an oral disclosure, use, exhibition or other means "P" document published prior to the international filing date but later than the priority date claimed "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art. "&" document member of the same patent family		
Date of the actual completion of the international search 15 November 2010		Date of mailing of the international search report 06/12/2010
Name and mailing address of the ISA/ European Patent Office, P.B. 5818 Patentlaan 2 NL - 2280 HV Rijswijk Tel. (+31-70) 340-2040, Fax: (+31-70) 340-3016		Authorized officer Roesch, Guillaume

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C(Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
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